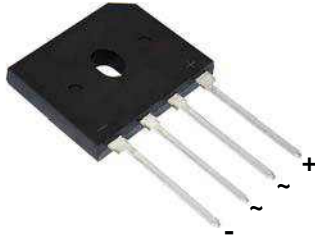
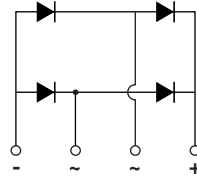




Glass Passivated Single-Phase Bridge Rectifier



Case Style GBU



Case Style GBU



RoHS COMPLIANT HALOGEN FREE

FEATURES

- UL recognition file number E54214
- Ideal for printed circuit boards
- High surge current capability
- High case dielectric strength of 1500 V_{RMS}
- Solder dip 275 °C max. 10 s, per JESD 22-B106
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

TYPICAL APPLICATIONS

General purpose use in AC/DC bridge full wave rectification for monitor, TV, printer, switching mode power supply, adapter, audio equipment, and home appliances applications.

MECHANICAL DATA

Case: GBU
Molding compound meets UL 94 V-0 flammability rating Base P/N-M3 - halogen-free, RoHS-compliant, and commercial grade

Terminals: Matte tin plated leads, solderable per J-STD-002 and JESD 22-B102
M3 suffix meets JESD 201 class 1A whisker test

Polarity: As marked on body

Mounting Torque: 10 cm-kg (8.8 inches-lbs) max.

Recommended Torque: 5.7 cm-kg (5 inches-lbs)

PRIMARY CHARACTERISTICS	
Package	GBU
I _{F(AV)}	4.0 A
V _{RRM}	50 V, 100 V, 200 V, 400 V, 600 V, 800 V, 1000 V
I _{FSM}	150 A
I _R	5 μA
V _F at I _F = 4.0 A	1.0 V
T _J max.	150 °C
Diode variations	In-line

MAXIMUM RATINGS (T _A = 25 °C unless otherwise noted)									
PARAMETER	SYMBOL	GBU4A	GBU4B	GBU4D	GBU4G	GBU4J	GBU4K	GBU4M	UNIT
Maximum repetitive peak reverse voltage	V _{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS voltage	V _{RMS}	35	70	140	280	420	560	700	V
Maximum DC blocking voltage	V _{DC}	50	100	200	400	600	800	1000	V
Maximum average forward rectified output current at	I _{F(AV)}	4.0							A
		3.0							
Peak forward surge current single sine-wave superimposed on rated load	I _{FSM}	150							A
Rating for fusing (t < 8.3 ms)	I ² t	93							A ² s
Operating junction and storage temperature range	T _J , T _{STG}	-55 to +150							°C

Notes

- (1) Unit case mounted on 1.6" x 1.6" x 0.06" thick (4.0 cm x 4.0 cm x 0.15 cm) aluminum plate
- (2) Units mounted on PCB with 0.5" x 0.5" (12 mm x 12 mm) copper pads and 0.375" (9.5 mm) lead length



ELECTRICAL CHARACTERISTICS ($T_A = 25\text{ }^\circ\text{C}$ unless otherwise noted)										
PARAMETER		SYMBOL	GBU4A	GBU4B	GBU4D	GBU4G	GBU4J	GBU4K	GBU4M	UNIT
Maximum instantaneous forward drop per diode	4.0 A	V_F					1.0			V
Maximum DC reverse current at rated DC blocking voltage per diode	$T_A = 25\text{ }^\circ\text{C}$	I_R					5.0			μA
	$T_A = 125\text{ }^\circ\text{C}$						500			
Typical junction capacitance per diode	4.0 A, 1 MHz	C_J					57			pF

THERMAL CHARACTERISTICS ($T_A = 25\text{ }^\circ\text{C}$ unless otherwise noted)										
PARAMETER		SYMBOL	GBU4A	GBU4B	GBU4D	GBU4G	GBU4J	GBU4K	GBU4M	UNIT
Typical thermal resistance		$R_{\theta JA}^{(2)}$					22			$^\circ\text{C/W}$
		$R_{\theta JC}^{(1)}$					4.2			

Notes

- (1) Unit case mounted on aluminum plate heatsink
- (2) Units mounted on PCB with 0.5" x 0.5" (12 mm x 12 mm) copper pads and 0.375" (9.5 mm) lead length

ORDERING INFORMATION (Example)				
PREFERRED P/N	UNIT WEIGHT (g)	PREFERRED PACKAGE CODE	BASE QUANTITY	DELIVERY MODE
GBU4J-M3/45	3.565	45	20	Tube
GBU4J-M3/51	3.565	51	250	Paper tray

RATINGS AND CHARACTERISTICS CURVES ($T_A = 25\text{ }^\circ\text{C}$ unless otherwise noted)

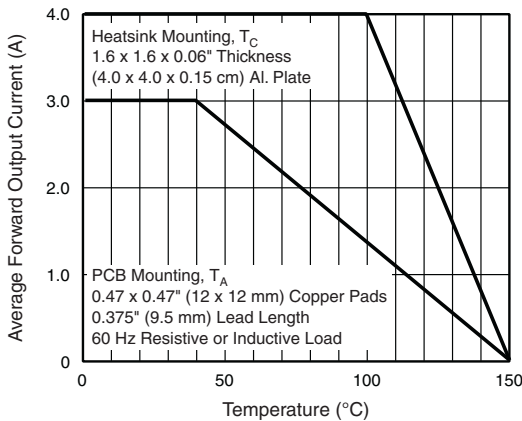


Fig. 1 - Derating Curve Output Rectified Current

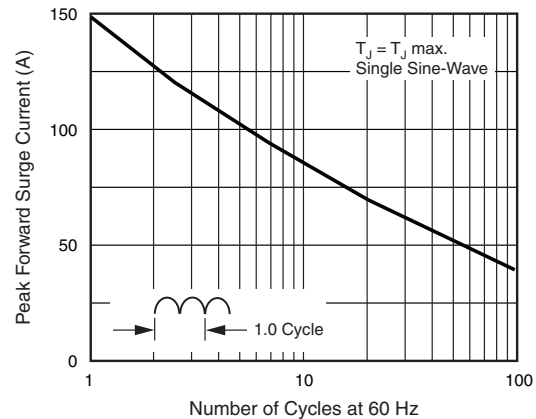


Fig. 2 - Maximum Non-Repetitive Peak Forward Surge Current Per Diode

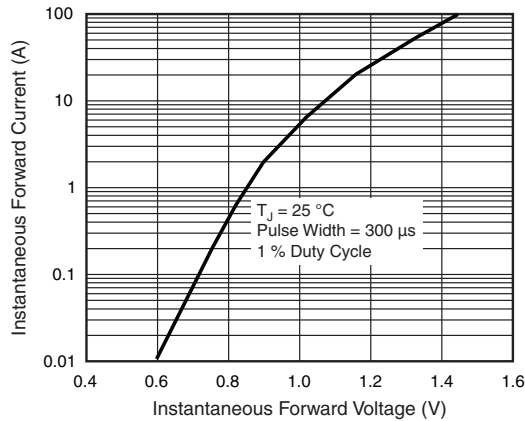


Fig. 3 - Typical Forward Characteristics Per Diode

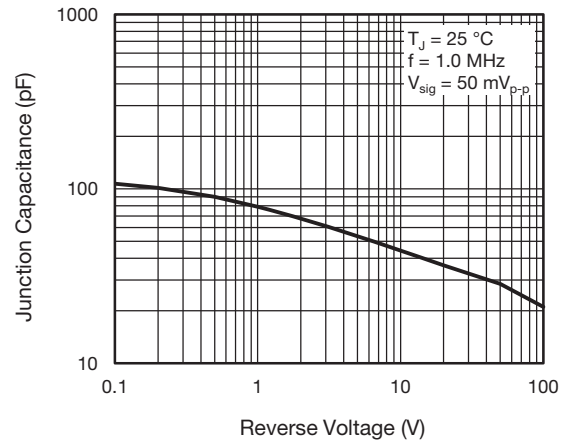


Fig. 5 - Typical Junction Capacitance Per Diode

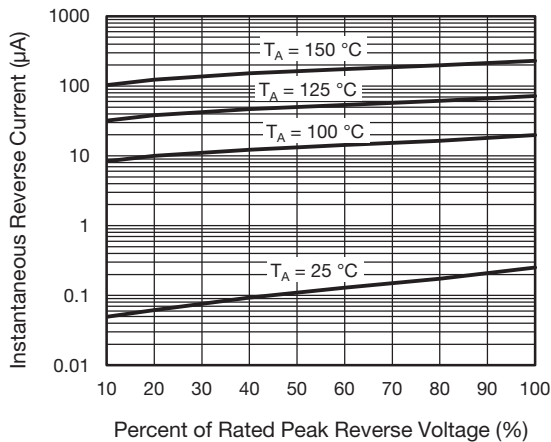


Fig. 4 - Typical Reverse Leakage Characteristics Per Diode

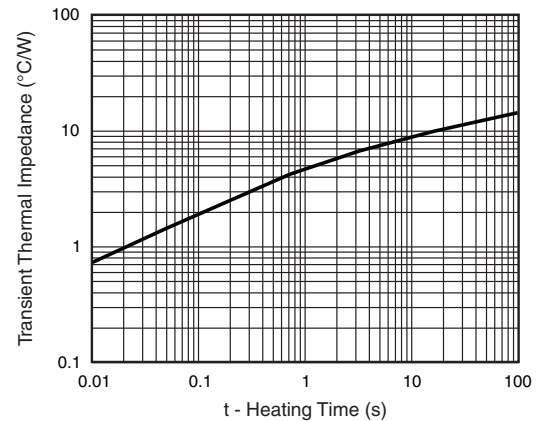
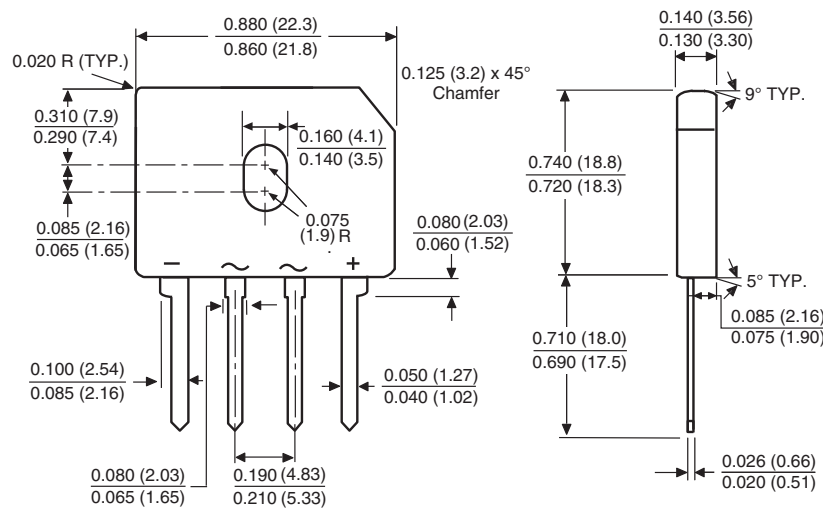


Fig. 6 - Typical Transient Thermal Impedance

PACKAGE OUTLINE DIMENSIONS in inches (millimeters)

Case Type GBU



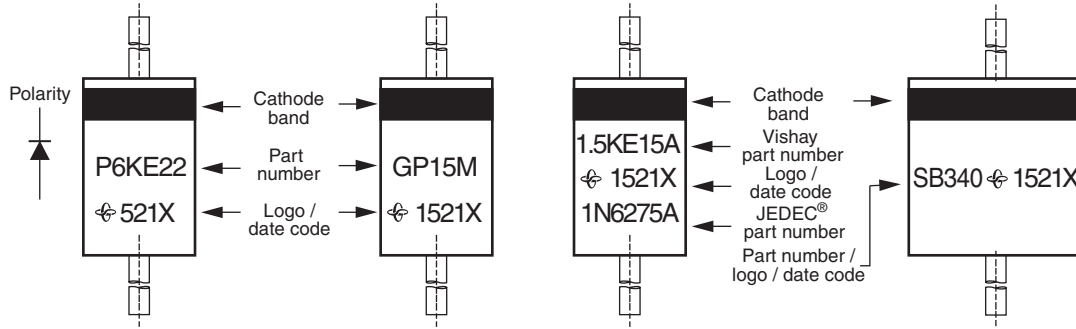
Polarity shown on front side of case, positive lead by beveled corner

Vishay General Semiconductor

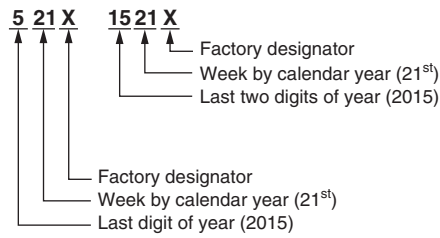
AXIAL MARKING

Package: DO-41 (DO-204AL), DO-15 (DO-204AC), DO-201AD, GP20, 1.5KE, P600

Examples:



DATE CODE (for RoHS-compliant products)

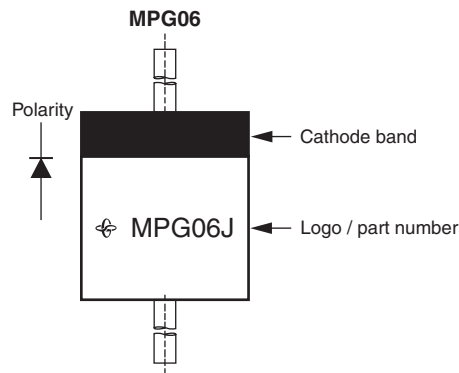


DATE CODE (for halogen-free products)



Notes

- (1) No cathode band marking for TVS bi-directional type
- (2) Date code per individual part number specification



PART NUMBER MARKING CODE		
TYPE	RoHS-COMPLIANT	HALOGEN-FREE
MPG06 series	MPG06x	M06x
RMPG06 series	RMPG06x	MR06x
UG06 series	UG06x	MUG06x
SB0x series	SB0x0	MSB0x0
TPMP06 series	T-x	MT-x

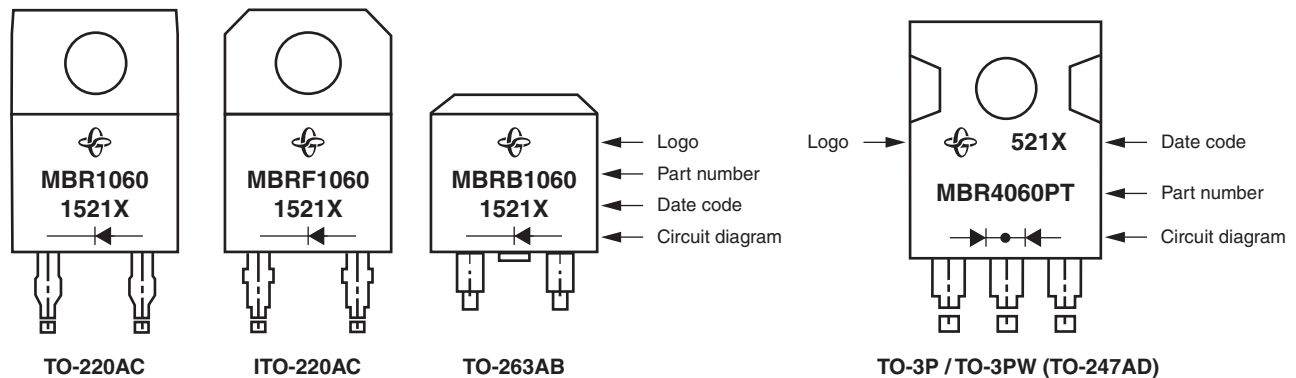
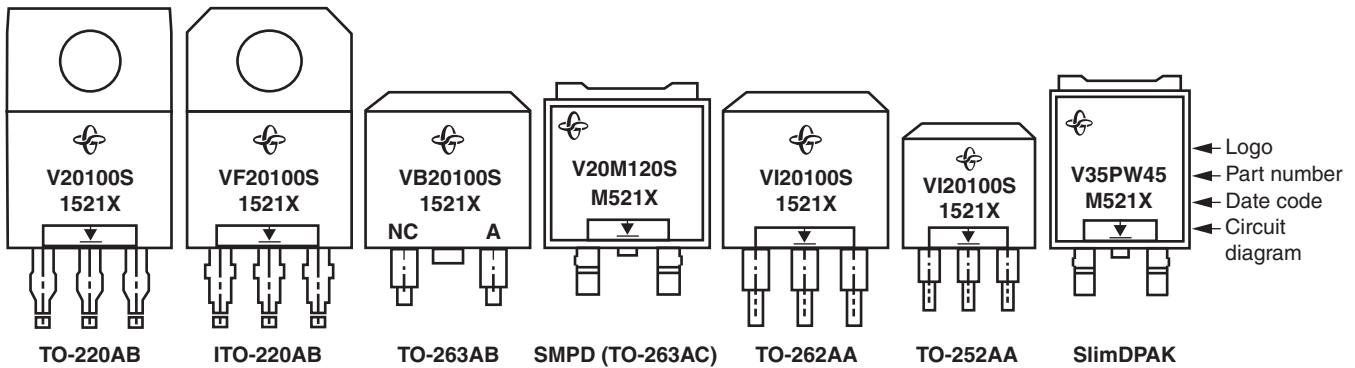
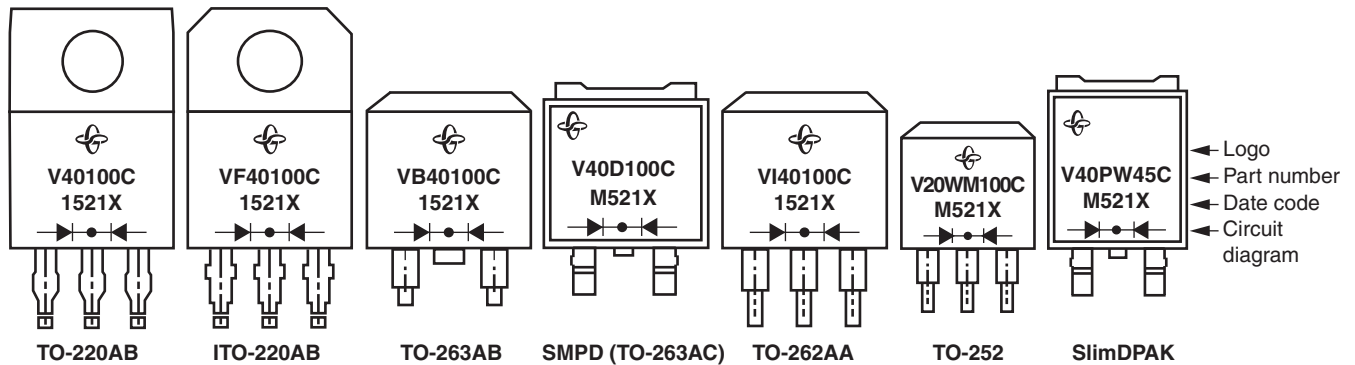
Note

- x - type code

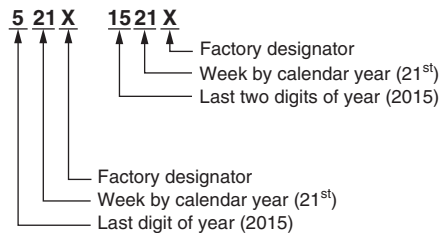


POWER PACK MARKING

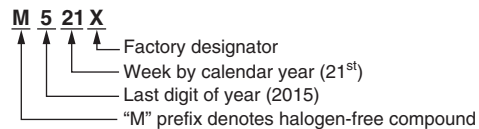
Examples:



DATE CODE (for RoHS-compliant products)



DATE CODE (for halogen-free products)



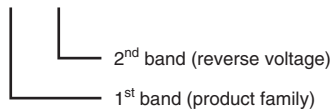
Notes

(1) Date code per individual part number specification

PLASTIC MELF AND MiniMELF MARKING

1. Package: GL41 (DO-213AB)

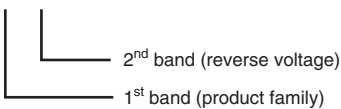
MELF
2.5 mm x 4.9 mm



TYPE	1 st BAND	2 nd BAND	
BYM10 series	white	gray: 50 V	violet: 1000 V
GL41 series	white	red: 100 V	white: 1300 V
BYM11 series	red	orange: 200 V	brown: 1600 V
RGL41 series	red	yellow: 400 V	
BYM12 series	green	green: 600 V	
EGL41 series	green	blue: 800 V	
BYM13 series	orange	gray: 20 V orange: 40 V green: 60 V	
SGL41 series	orange	red: 30 V yellow: 50 V	
TGL41-xx	blue		
ZGL41-xx	red		

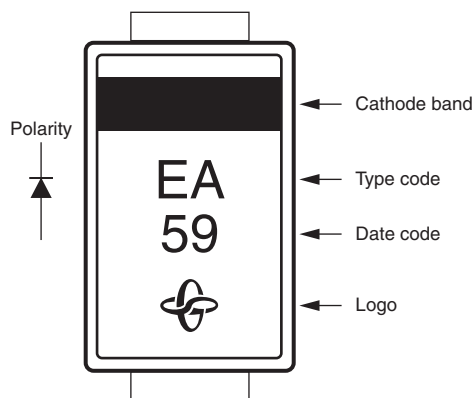
2. Package: GL34 (DO-213AA)

MiniMELF
1.6 mm x 3.5 mm

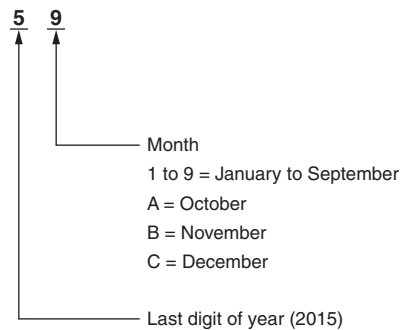


TYPE	1 st BAND	2 nd BAND	
BYM07 series	white	gray: 50 V	brown: 300 V
GL34 series	white	red: 100 V	yellow: 400 V
EGL34 series	green	pink: 150 V	green: 600 V
RGL34 series	red	orange: 200 V	blue: 800 V

GF1 (DO-214BA) MARKING



DATE CODE

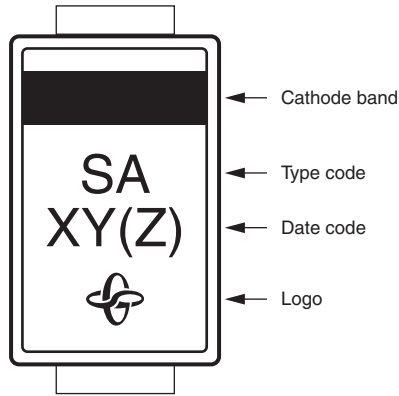


Note

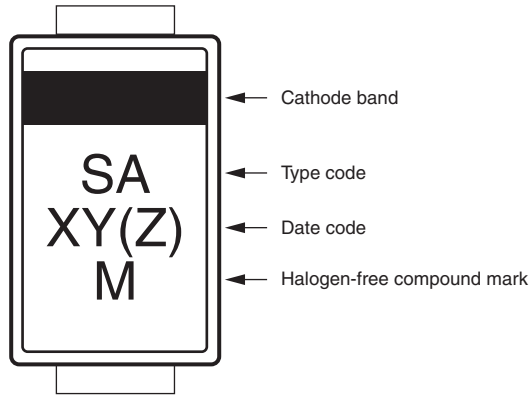
- Type code refers to individual datasheet

SMA (DO-214AC), SMB (DO-214AA), SMC (DO-214AB), SlimSMA (DO-221AC), AND SMPA (DO-221BC) MARKING

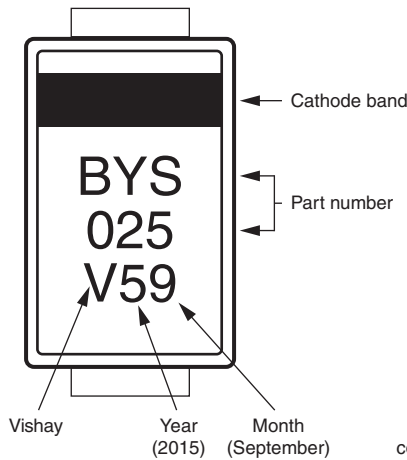
SMA, SMB, SMC



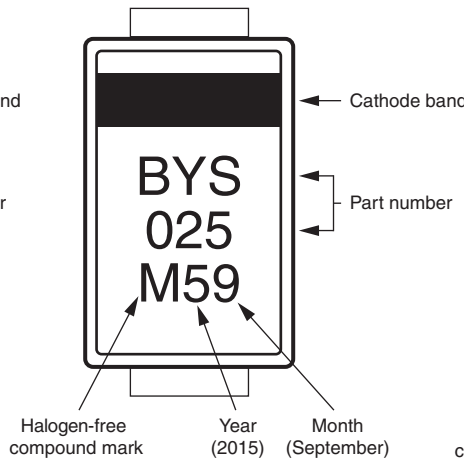
SMA, SMB, SMC, SlimSMA, SMPA



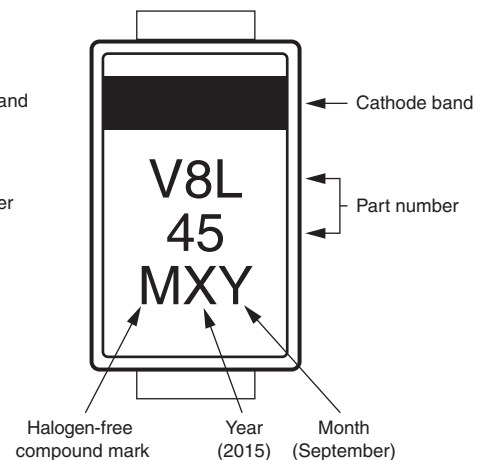
SMA with "BYS", "BYG" Prefix



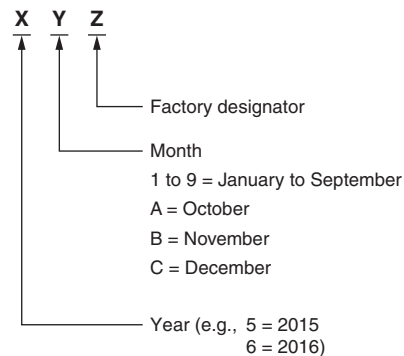
SMA with "BYS", "BYG" Prefix



SMA, SMB, SMC (for TMBS products with long core part number)



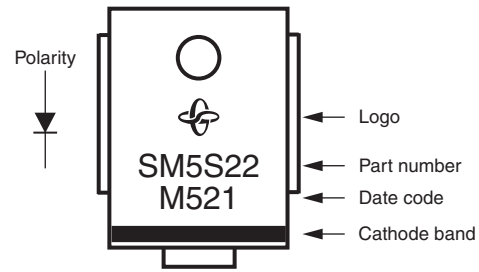
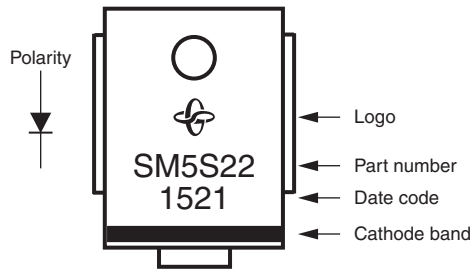
DATE CODE



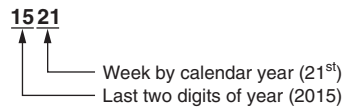
Notes

- Type code refers to individual datasheet
- No cathode band marking for TVS bi-directional type
- "XY" 2 digits: For rectifiers and PAR TVS (TPSMA, TPSMB, TPSMC, and TA6F)
- "XYZ" 3 digits: For TRANSORB® TVS and Power Voltage-Regulating Diodes
- Non "M" mark belongs to RoHS-compliant product

DO-218AB MARKING



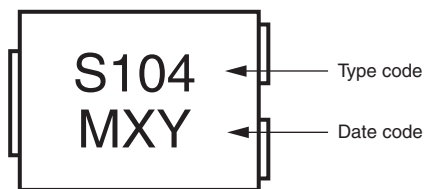
DATE CODE (for RoHS-compliant products)



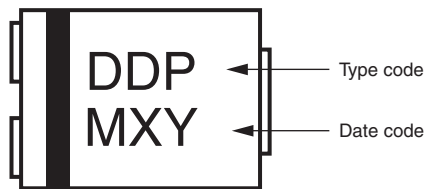
DATE CODE (for halogen-free products)



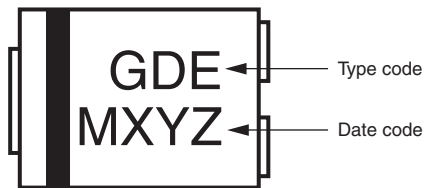
SMPC (TO-277A) MARKING



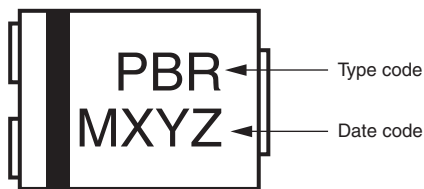
Polarity —|◀ (for rectifiers)



Polarity —|◀ (for PAR[®] TVS)

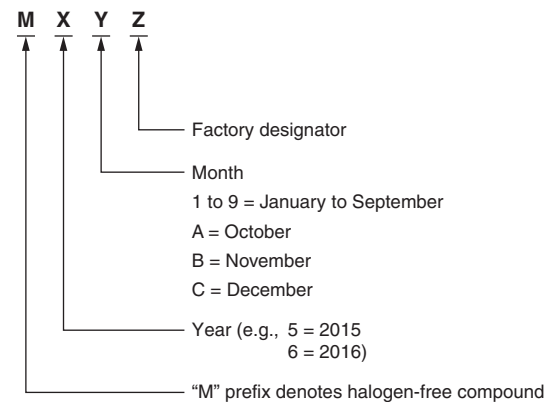


Polarity —|◀ (for TRANSZORB[®] TVS of SMPCxxAN)



Polarity —|◀ (for TRANSZORB[®] TVS of SMPCxxA)

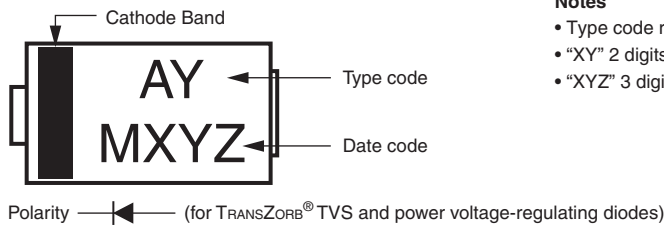
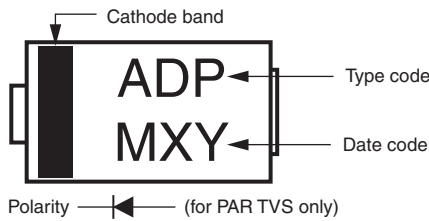
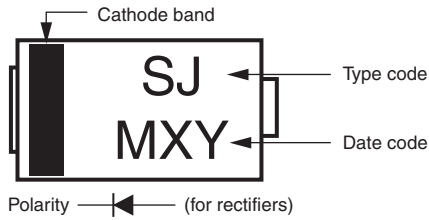
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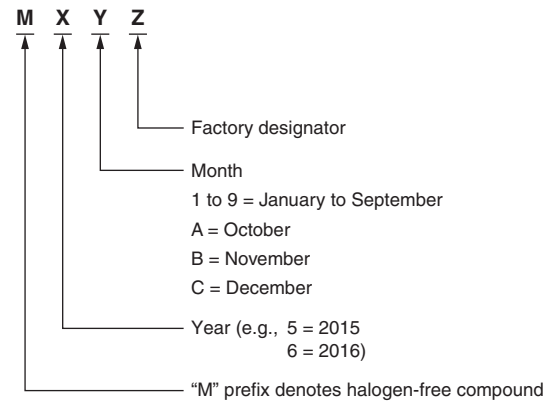
Notes

- Type code refers to individual datasheet
- "XY" 2 digits: for rectifiers and PAR[®] TVS
- "XYZ" 3 digits: for TRANSZORB[®] TVS
- TRANSZORB[®] TVS: cathode band depends on actual polarity
- No cathode band marking for bi-directional PAR TVS type

SMP (DO-220AA) MARKING



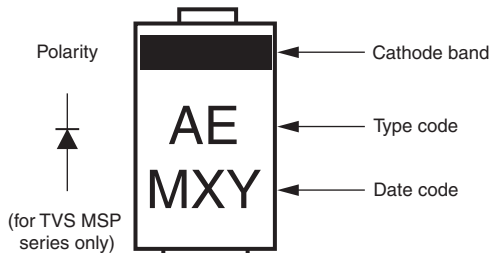
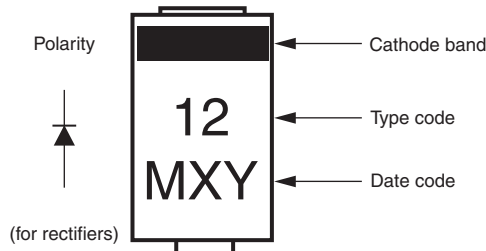
DATE CODE



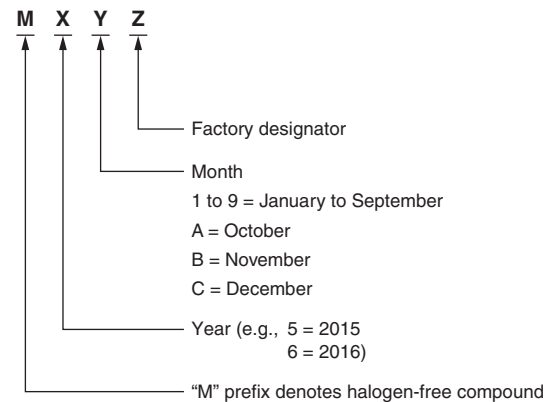
Notes

- Type code refers to individual datasheet
- "XY" 2 digits: for rectifiers and PAR TVS
- "XYZ" 3 digits: for TRANSZORB® TVS and power voltage-regulating diodes

MicroSMP (DO-219AD) MARKING



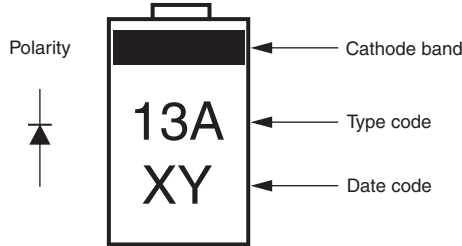
DATE CODE



Note

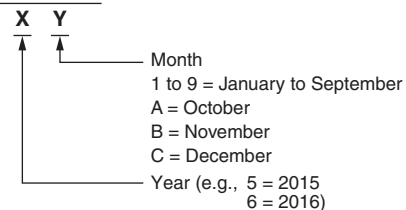
- Type code refers to individual datasheet

MicroSMF (DO-219AC) MARKING

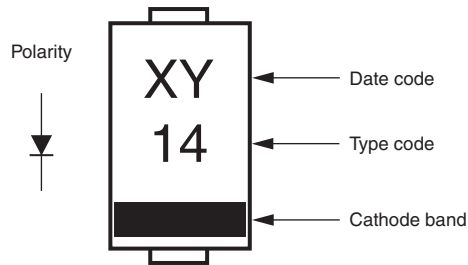


- Note**
- Type code refers to individual datasheet

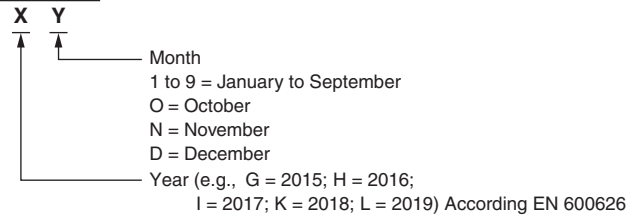
DATE CODE



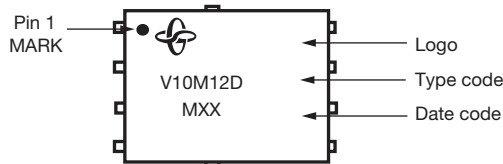
SMF (DO-219AB) MARKING



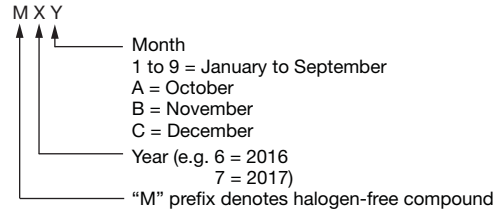
DATE CODE



FlatPAK 5 X 6 MARKING

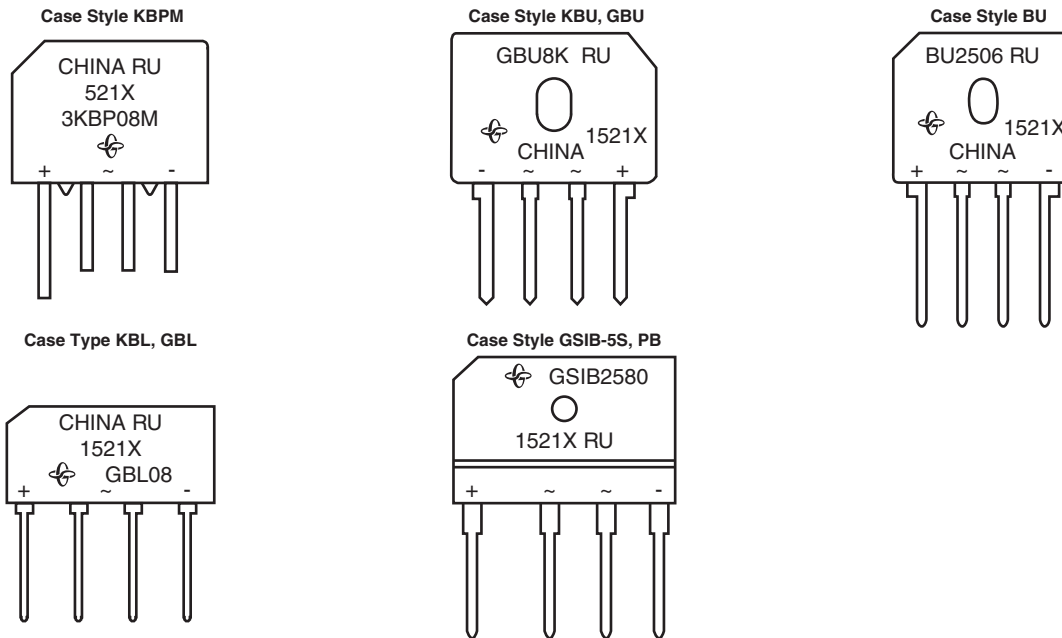


DATE CODE



BRIDGE MARKING

Single in-line bridge marking



Logo :

Part number: 3KBP08M, BU2506 (example)
 UL approved: RU
 Location: China
 Date code (e.g., 521X, 1521X or M521X)
 Polarity: + Positive output terminal
 - Negative output terminal
 ~ Alternate

DATE CODE (for RoHS-compliant products)



DATE CODE (for RoHS-compliant products)



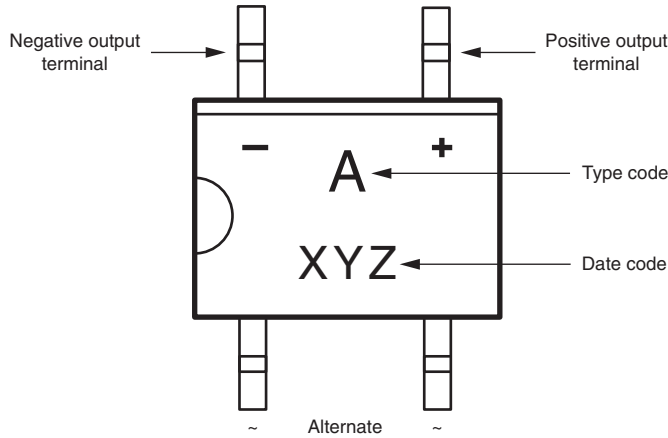
DATE CODE (for halogen-free products)



Note
 (1) Date code per individual part number specification

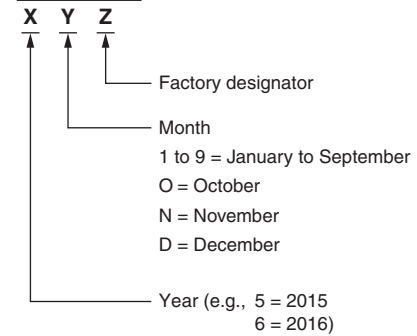
DUAL IN-LINE BRIDGE MARKING

MBS (TO-269AA) and MBM Mini-Bridge



Polarity: + Positive output terminal
- Negative output terminal

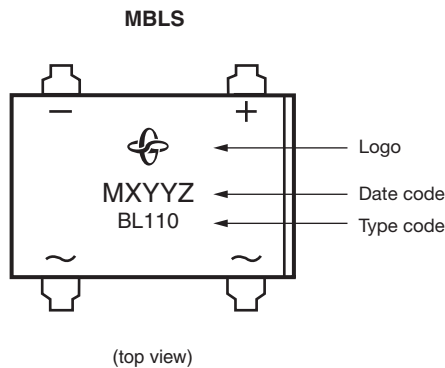
DATE CODE



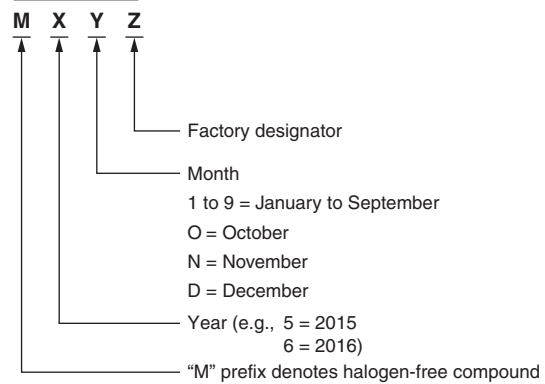
TYPE	TYPE CODE	TYPE	TYPE CODE
B2S, B2M	B2	MB4S, MB4M	4
B4S, B4M	B4	MB6S, MB6M	6
B6S, B6M	B6	RMB2S	2R
MB2S, MB2M	2	RMB4S	4R

Note

- For halogen-free: add "Underline" below type code (e.g., 6)
- RMB2S and RMB4S only has type code without date code

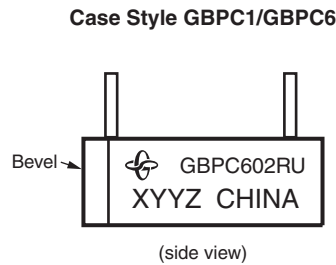
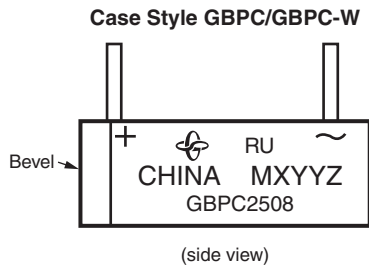
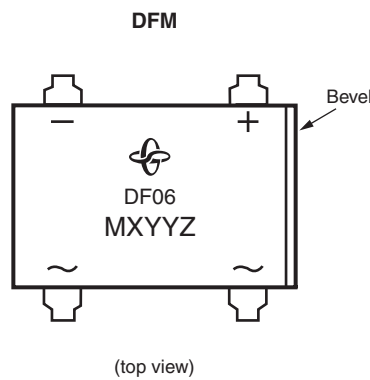
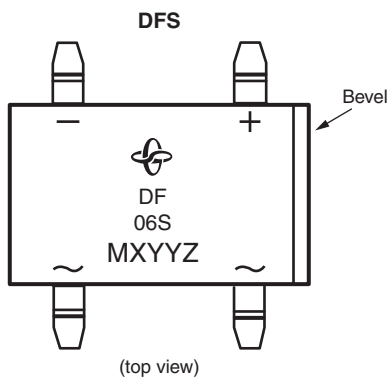
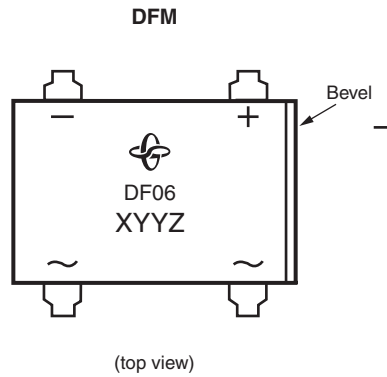
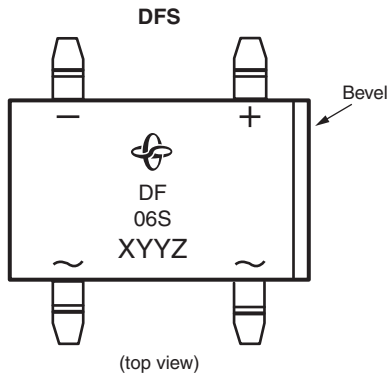


DATE CODE



TYPE	TYPE CODE
MBL104S	BL104
MBL106S	BL106
MBL108S	BL108
MBL110S	BL110

DFS, DFM, and WOG



Logo:

Part number: GBPC2508 (example)
 UL approved: RU
 Location: China
 Date code: (M)XYYZ
 Polarity: + Positive output terminal
 - Negative output terminal
 ~ Alternate

DATE CODE

M XYYZ

Diagram showing the breakdown of the date code M XYYZ. Arrows point from the text to the corresponding parts of the code: "M" is the factory designator, "X" is the week by calendar year (21st), "Y" is the last digit of year (2015), and "Z" is the "M" prefix denoting halogen-free compound.

Factory designator
 Week by calendar year (21st)
 Last digit of year (2015)
 "M" prefix denotes halogen-free compound

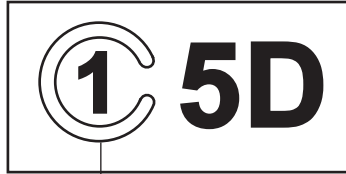
Notes

- (1) Date code per individual part number specification
- (2) Non "M" mark belongs to RoHS-compliant product
- (3) "M" prefix denotes halogen-free compound

Vishay Semiconductors (Small Signal Products)

SMD MARKING

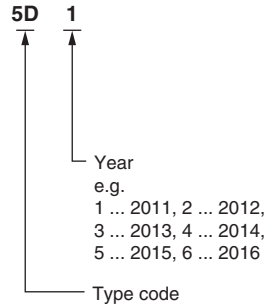
CLP0603 MARKING



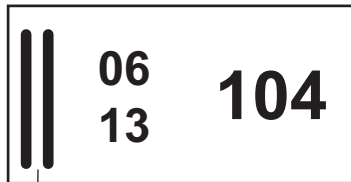
Cathode mark
Opening of "C" indicates month,
where wafer lot was started in fab,
e.g. 3 o'clock means March

Note
• Type code refers to individual datasheet

DATE CODE



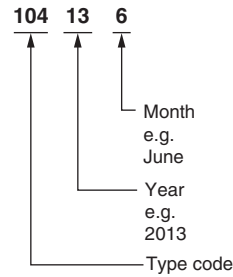
CLP1608 MARKING



Cathode mark

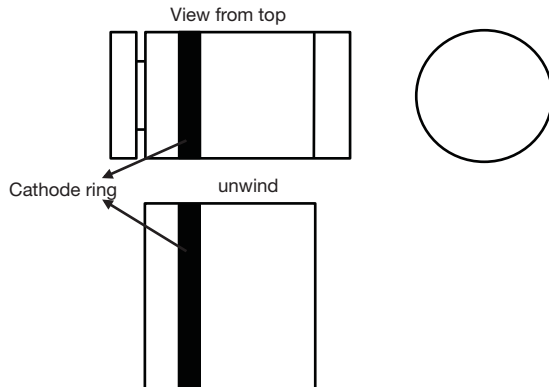
Note
• Type code refers to individual datasheet

DATE CODE

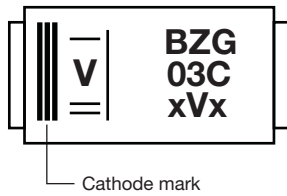


DO-213 MARKING

Marking: cathode

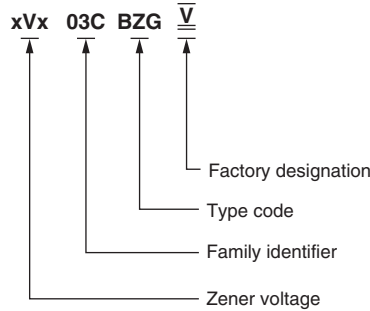


SMA (DO-214AC) MARKING

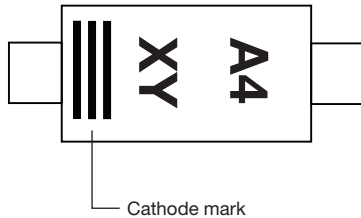


Note
• Type code refers to individual datasheet

DATE CODE

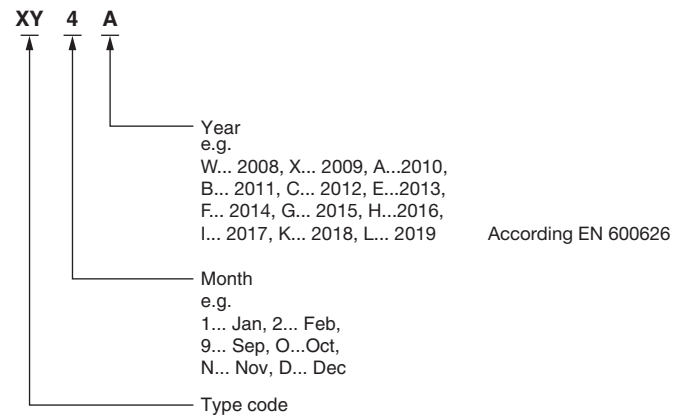


SMF (DO-219AB) MARKING

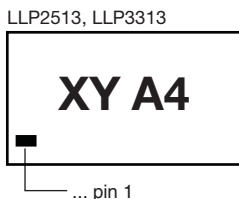
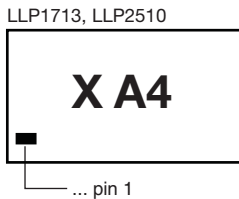


Note
• Type code refers to individual datasheet

DATE CODE

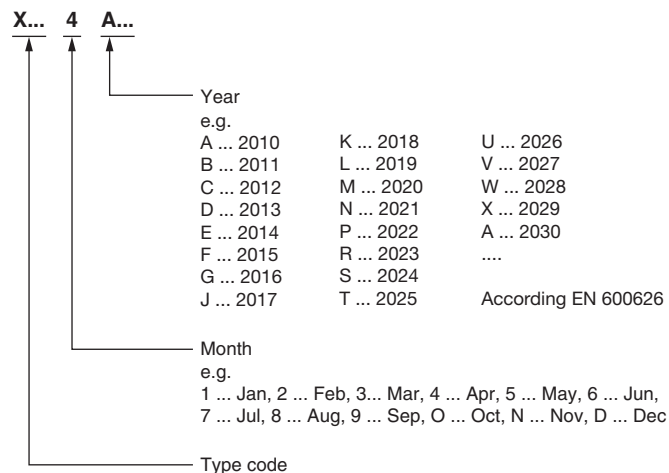


LLP75, LLP1713, LLP2510, LLP2513, LLP3313 MARKING

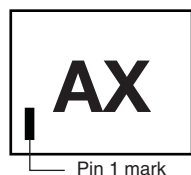


Note
• Type code refers to individual datasheet

DATE CODE



LLP1006, LLP1010 MARKING



Note
• Type code refers to individual datasheet

DATE CODE

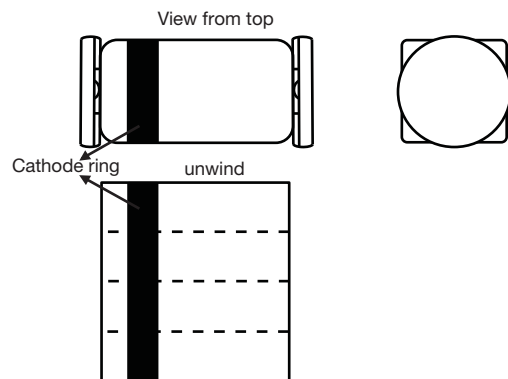
X... A...

Jan14-A, Feb14-B, Mar14-C, Apr14-D, May14-E, Jun14-F, Jul14-G, Aug14-H, Sep14-J, Oct14-K, Nov14-M, Dec14-N, Jan15-P, Feb15-Q, Mar15-R, Apr15-S, May15-T, Jun15-U, Jul15-V, Aug15-W, Sep15-X, Oct15-Y, Nov15-Z, Dec15- ν , Jan16- ϑ , Feb16- ζ , Mar16- ζ , Apr16- ζ , May16- ζ , Jun16- ζ , Jul16- ζ , Aug16- ζ , Sep16- ζ , Oct16- ζ , Nov16- ζ , Dec16- ζ , Jan17-L, Feb17- Π , Mar17- Λ , Apr17-M, May17- λ , Jun17-1, Jul17-2, Aug17-3, Sep17-4, Oct17-5, Nov17-6, Dec17-7, Jan18 = Jan14,....

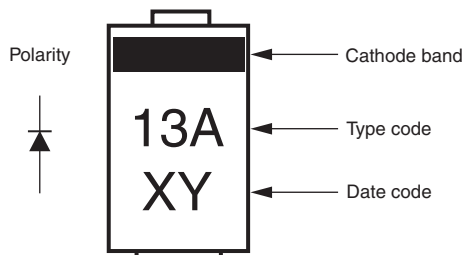
Type code

MicroMELF MARKING

Marking: cathode



MicroSMF (DO-219AC) MARKING



Note
• Type code refers to individual datasheet

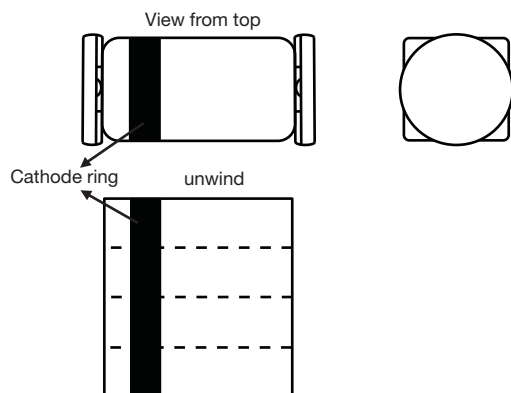
DATE CODE

X Y

Month
1 to 9 = January to September
A = October
B = November
C = December
Year (e.g., 5 = 2015
6 = 2016)

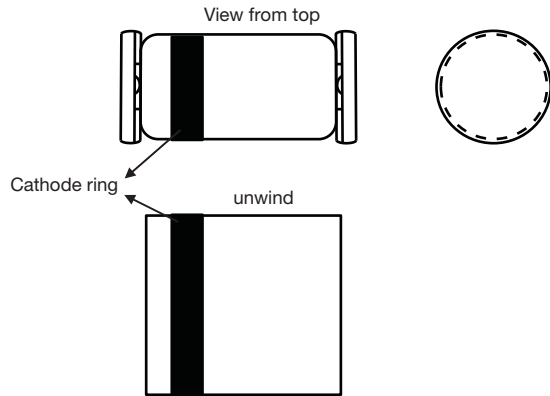
QuadroMELF (SOD-80) MARKING

Marking: cathode



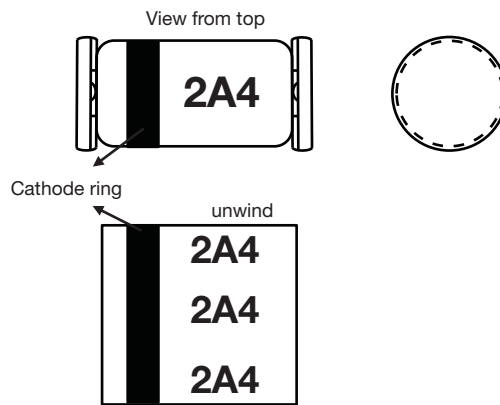
MiniMELF (SOD-80) MARKING

Marking: cathode

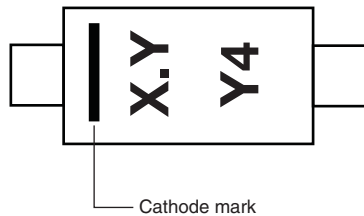


MiniMELF (SOD-80) TLZ MARKING

Marking: type and cathode

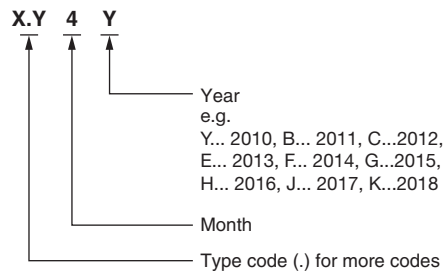


SOD-123 MARKING



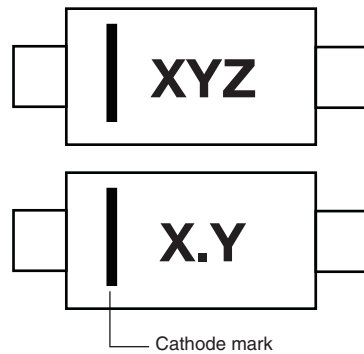
Note
• Type code refers to individual datasheet

DATE CODE

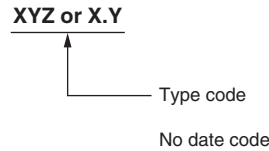


According to EN 600626

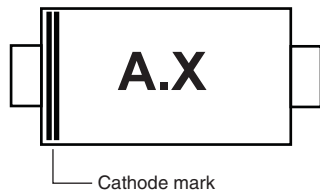
SOD-323 MARKING



Note
• Type code refers to individual datasheet

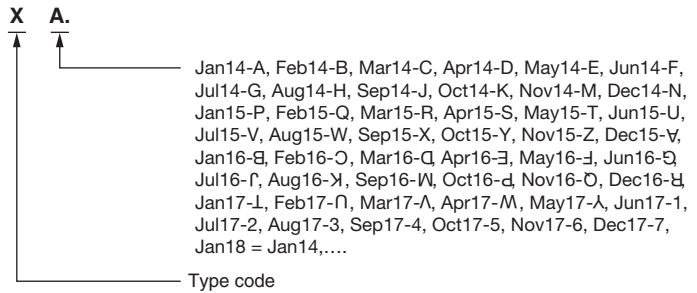


SOD-523 MARKING

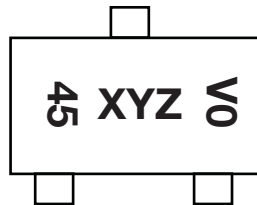


Note
• Type code refers to individual datasheet

DATE CODE

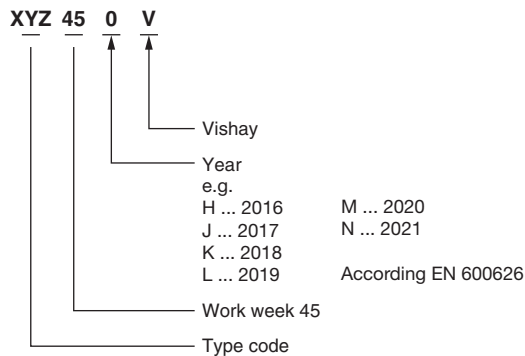


SOT-23 MARKING

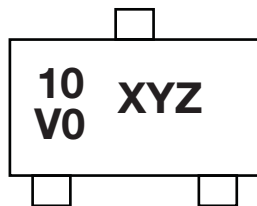


Note
• Type code refers to individual datasheet

DATE CODE

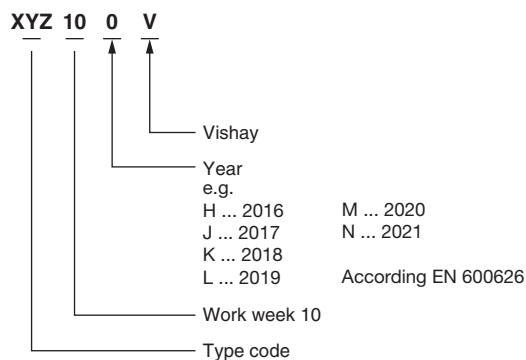


SOT-3xx MARKING



Note
• Type code refers to individual datasheet

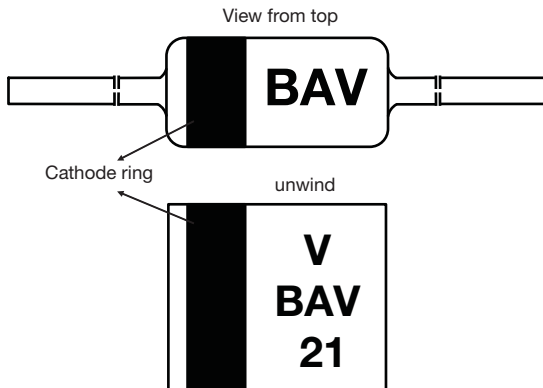
DATE CODE



AXIAL MARKING

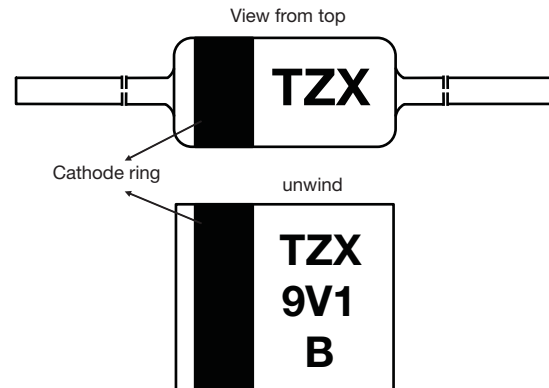
DO-35 (DO-204AH) BAV, BAW, BAS MARKING

Marking: type and cathode



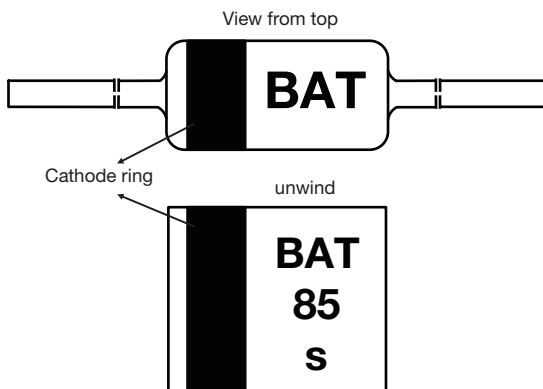
DO-35 (DO-204AH) ZENER TZX MARKING

Marking: type and cathode



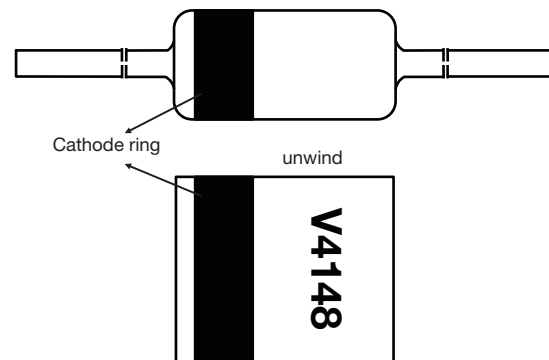
DO-35 (DO-204AH) SCHOTTKY BAT, SD MARKING

Marking: type and cathode



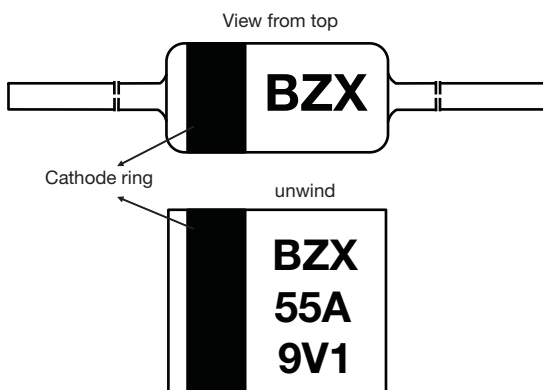
DO-35 (DO-204AH) 1N4148 MARKING

Marking: type and cathode



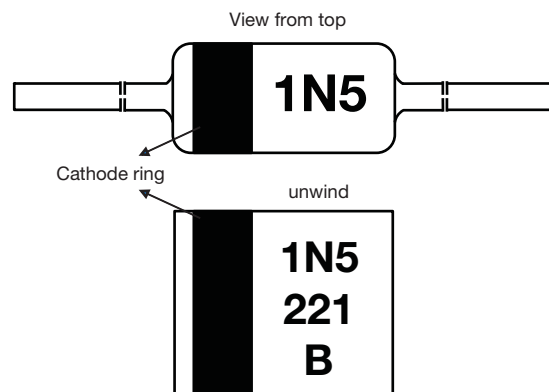
DO-35 (DO-204AH) ZENER BZX55 MARKING

Marking: type and cathode



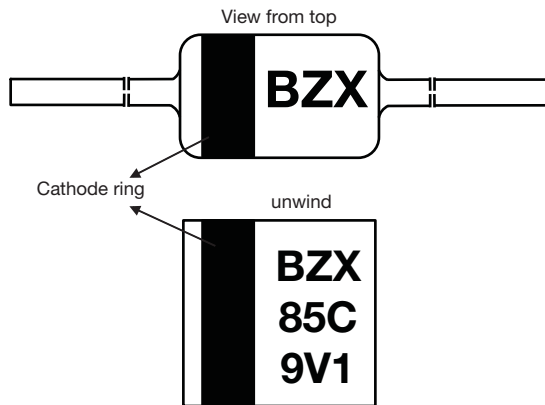
DO-35 (DO-204AH) ZENER 1N52 MARKING

Marking: type and cathode



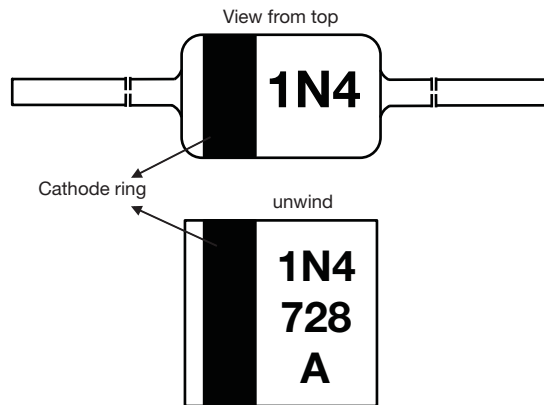
DO-41 (DO-204AL) BZX85 MARKING

Marking: type and cathode



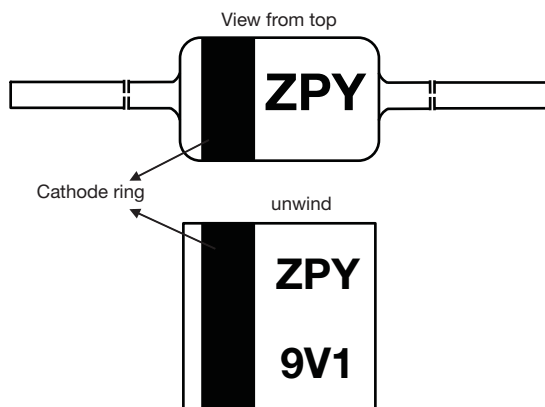
DO-41 (DO-204AL) 1N47xx MARKING

Marking: type and cathode

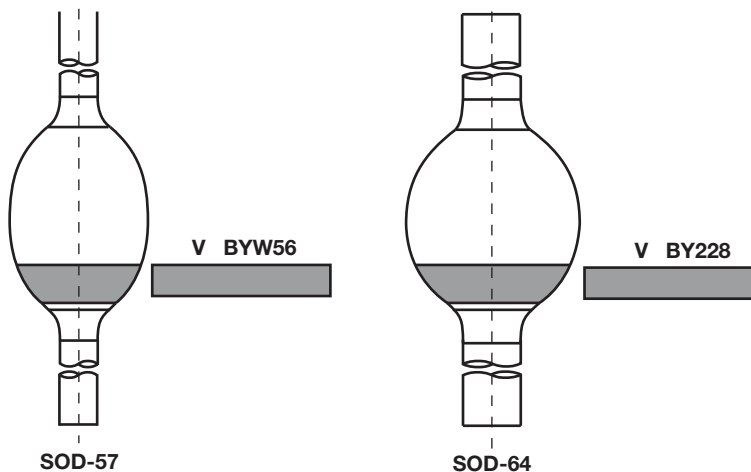


DO-41 (DO-204AL) ZPY MARKING

Marking: type and cathode



SOD-57, SOD-64 MARKING CODE



SOD-57 and SOD-64 Avalanche diodes

The unique part number is followed by letter "V", means Vishay
e.g. BYT62 V; SF1600 V or BYW83 V

SOD-57 Zener diodes

BZT03Cxx - where "xx" means the Zener voltage (no "V" after the part number)

SOD-64 Zener diodes

BZW03Cxx - where "xx" means the Zener voltage (no "V" after the part number)

Vishay Semiconductors (High Power Products)

SMF (DO-219AB) MARKING



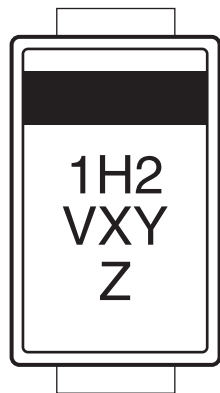
1st row

First digit: year (E = 2013; F = 2014; G = 2015; H = 2016; I = 2017; K = 2018; L = 2019.....) According to EN 600626
Second digit: month (1 = Jan; 2 = Feb; ... O = Oct; N = Nov; D = Dec)

2nd row

First digit: environmental digit
Second digit: current / voltage rating

SMA (DO-214AC), SMB (DO-214AA), SMC (DO-214AB) (FRED Pt®) MARKING



← Cathode band
← Type code
← Date code
← Environmental digit code

Type Code

1 H 2
Voltage
FRED Pt®
2 = 200 V
..
6 = 600 V

Current
1 = 1 A
..
5 = 5 A

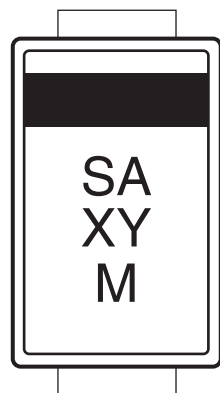
Date Code

X Y
Month:
1 to 9 = January to September
A = October
B = November
C = December

Year
(e.g. 1 = 2011, 2 = 2012)

Process type:
X = hyperfast recovery time
H = hyperfast recovery time
U = ultrafast recovery time
L = low V_f ultrafast recovery time

SMA (DO-214AC), SMB (DO-214AA), SMC (DO-214AB) (Schottky) MARKING



← Cathode band
← Type code
← Date code
← Halogen-free compound mark

Type Code

S A
Voltage
Schottky standard:
C = 15 V
E = 30 V
F = 40 V
H = 60 V
J = 100 V

Current
1 = 1 A
X = 1.5 A
2 = 2 A
3 = 3 A
4 = 4 A
..
..

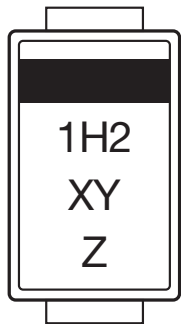
Date Code

X Y
Month:
1 to 9 = January to September
A = October
B = November
C = December

Year
(e.g. 1 = 2011, 2 = 2012)

Schottky MBR series:
2 = 20 V
3 = 30 V
4 = 40 V
6 = 60 V
9 = 90 V
0 = 100 V

SlimSMA (DO-221AC) MARKING



Type Code

1 H 2

Voltage
2 = 200 V
3 = 300 V
..

Current
1 = 1 A
..
5 = 5 A

Process type:
X = hyperfast recovery time
H = hyperfast recovery time
U = ultrafast recovery time
L = low V_F ultrafast recovery time

Date Code

X Y

Month:
1 to 9 = January to September
A = October
B = November
C = December

Year
(e.g. 1 = 2011, 2 = 2012)

SMPC MARKING



Polarity (For rectifiers)

1st row

F C H 2

Volt class
1 = 100 V
2 = 200 V
3 = 300 V
..

Family
H, U, X, L

C = common cathode
E = single die

Current

2nd row

M X Y

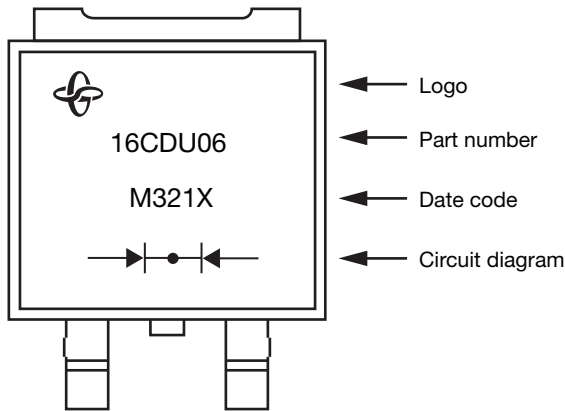
Month
1 to 9 = January to September
A = October
B = November
C = December

Year
1 = 2011
2 = 2012
..

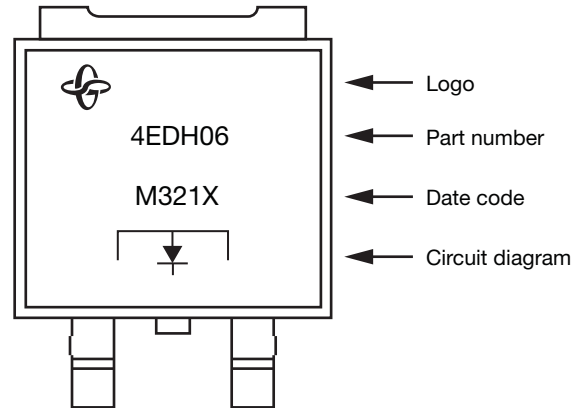
Environmental digit

CURRENT	DIGIT	CURRENT	DIGIT
1	D	8	Q
2	F	7	R
3	G	10	S
4	J	11	T
5	K	12	V
6	N	13	Y
7	P	14	Z

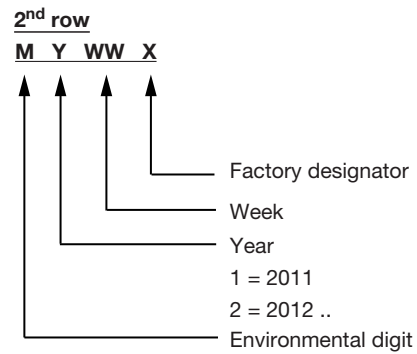
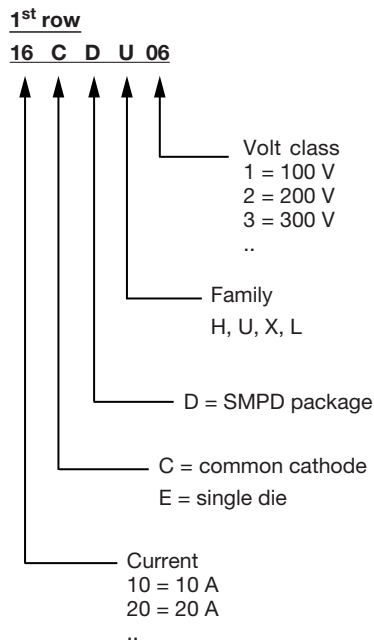
SMPD MARKING



(For Dual Die Parts)



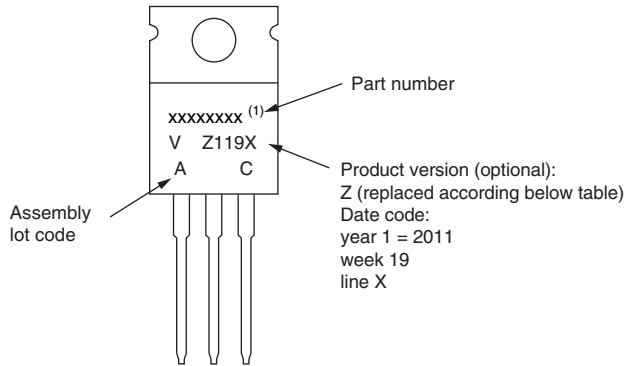
(For Single Die Parts)



TO-220 MARKING

Examples: TO-220AB, TO-220FP, TO-220AC E, TO-220AC-N3

TO-220AB E

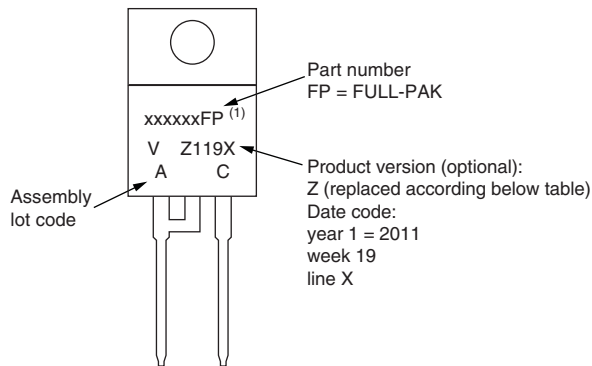


Example: This is a xxxxxxxx⁽¹⁾ with assembly lot code AC, assembled on WW 19, 2011 in the assembly line "X"

Note

⁽¹⁾ If part number contains "H" as last digit, product is AEC-Q101 qualified

TO-220FP-N3

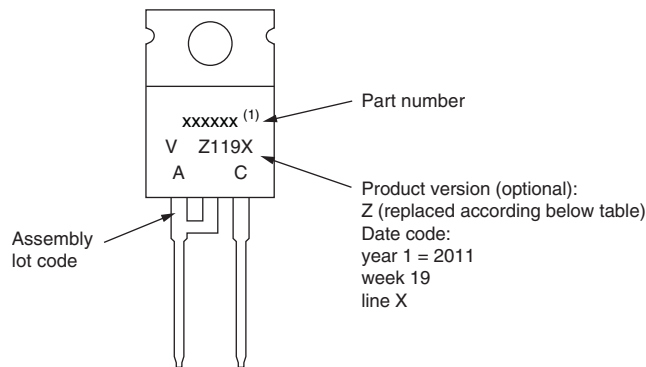


Example: This is a xxxxxxFP⁽¹⁾ with assembly lot code AC, assembled on WW 19, 2011 in the assembly line "X"

Note

⁽¹⁾ If part number contains "H" as last digit, product is AEC-Q101 qualified

TO-220AC E, TO-220AC-N3

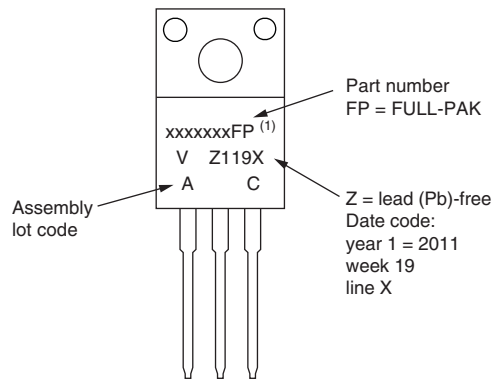


Example: This is a xxxxxx⁽¹⁾ with assembly lot code AC, assembled on WW 19, 2011 in the assembly line "X"

Note

⁽¹⁾ If part number contains "H" as last digit, product is AEC-Q101 qualified

TO-220FP 2L

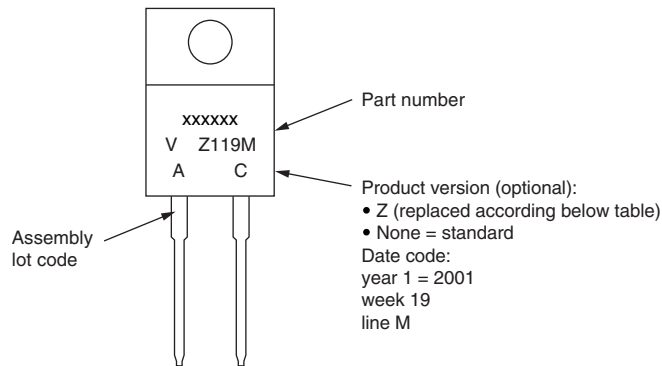


Example: This is a xxxxxxFP⁽¹⁾ with assembly lot code AC, assembled on WW 19, 2011 in the assembly line "X"

Note

⁽¹⁾ If part number contains "H" as last digit, product is AEC-Q101 qualified

TO-220AC 2L



Example: This is a xxxxxx with assembly lot code AC, assembled on WW 19, 2001 in the assembly line "M"

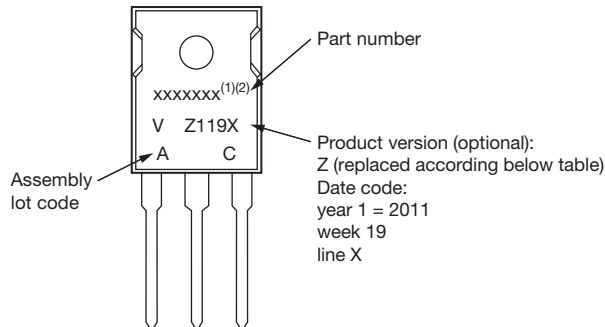
Note

⁽¹⁾ If part number contains "H" as last digit, product is AEC-Q101 qualified

TO-247 MARKING

Examples:

TO-247, 3 pins long-lead

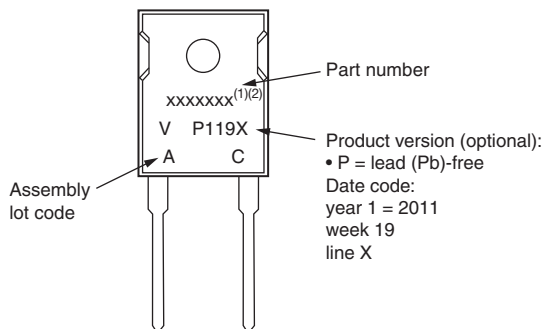


Example: This is a xxxxxxx⁽¹⁾ with assembly lot code AC, assembled on WW 19, 2011 in the assembly line "X"

Notes

- (1) If part number contains "H" as last digit, product is AEC-Q101 qualified
- (2) If part number contains "L", product is long-lead

TO-247, 2 pins long-lead

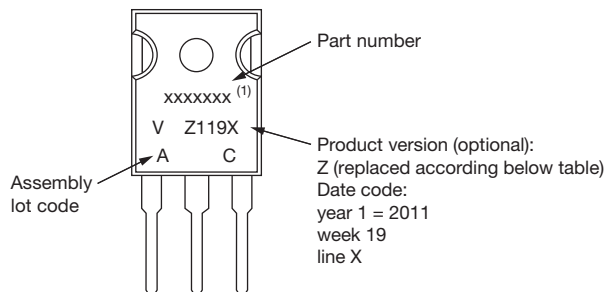


Example: This is a xxxxxxx with assembly lot code AC, assembled on WW 19, 2011 in the assembly line "X"

Notes

- (1) If part number contains "H" as last digit, product is AEC-Q101 qualified
- (2) If part number contains "L", product is long-lead

TO-247AC-N3

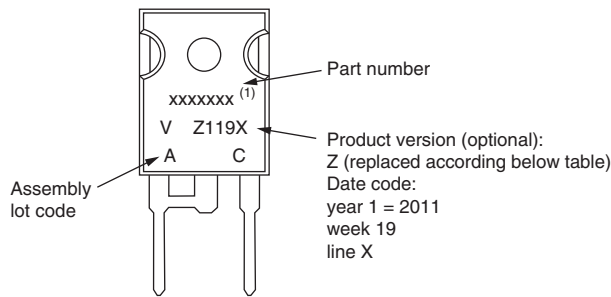


Example: This is a xxxxxxx⁽¹⁾ with assembly lot code AC, assembled on WW 19, 2011 in the assembly line "X"

Note

- (1) If part number contains "H" as last digit, product is AEC-Q101 qualified

TO-247AC-N3 modified

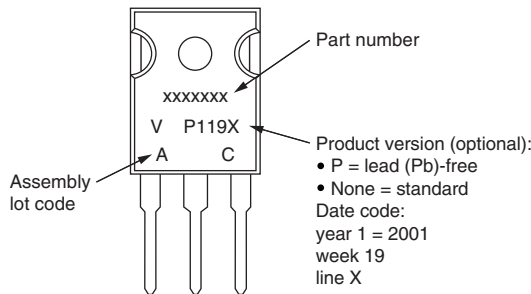


Example: This is a xxxxxx⁽¹⁾ with assembly lot code AC, assembled on WW 19, 2011 in the assembly line "X"

Note

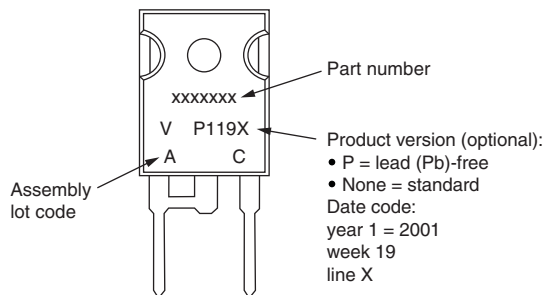
⁽¹⁾ If part number contains "H" as last digit, product is AEC-Q101 qualified

TO-247 PbF



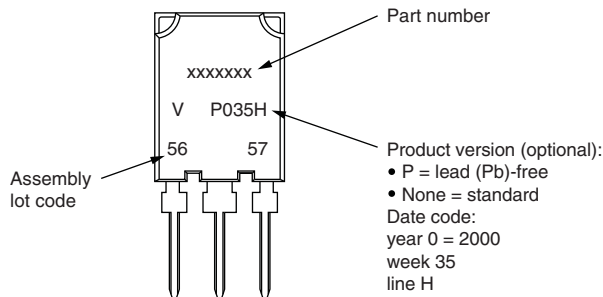
Example: This is a xxxxxx with assembly lot code AC, assembled on WW 19, 2001 in the assembly line "X"

TO-247 PbF modified



Example: This is a xxxxxx with assembly lot code AC, assembled on WW 19, 2001 in the assembly line "X"

Super TO-247

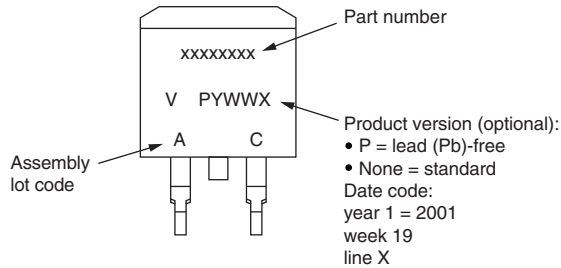


Example: This is a xxxxxx with assembly lot code 5657, assembled on WW 35, 2000 in assembly line "H"

D²PAK (TO-263AA), TO-262 MARKING

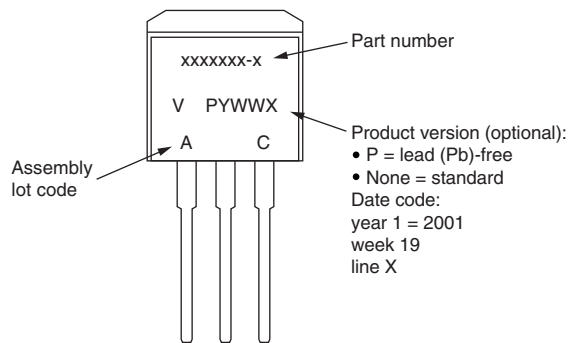
Examples:

D²PAK E (TO-263AA)



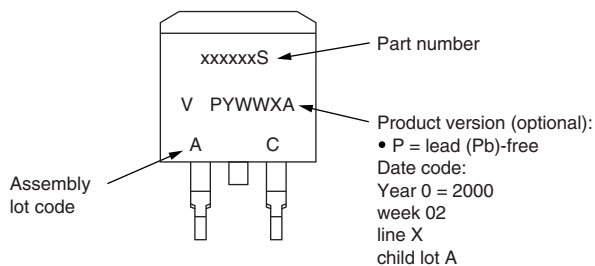
Example: This is a xxxxxxx with assembly lot code AC, assembled on WW 19, 2001 in the assembly line "X"

TO-262AA



Example: This is a xxxxxx-x with assembly lot code AC, assembled on WW 19, 2001 in the assembly line "X"

D²PAK (TO-263AA)

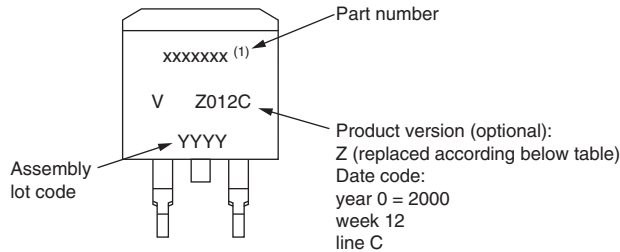


Example: This is a xxxxxS with assembly lot code AC, assembled on WW 02, 2000

DPAK (TO-252AA) MARKING

Examples:

DPAK E

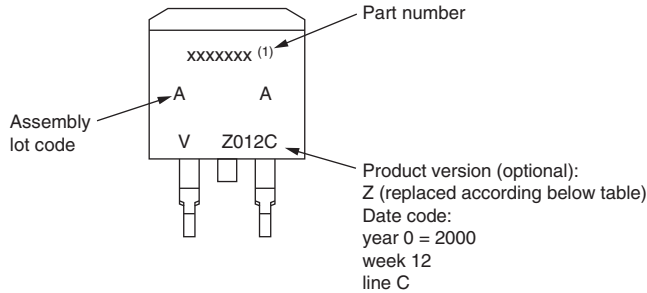


Example: This is a xxxxxxx with assembly lot code YYYY, assembled on WW 12, 2000 in the assembly line "C"

Note

(1) If part number contains "H" as last digit, product is AEC-Q101 qualified

DPAK



Example: This is a xxxxxxx with assembly lot code YYYY, assembled on WW 12, 2000 in the assembly line "C"

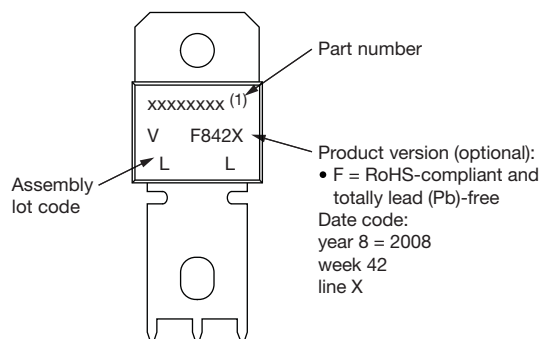
Note

(1) If part number contains "H" as last digit, product is AEC-Q101 qualified

PowerTab® MARKING

Examples:

PowerTab®



Example: This is a xxxxxxx (1) with assembly lot code LL, assembled on WW 42, 2008 in the assembly line "X"

Note

(1) If part number contains "H" as last digit, product is AEC-Q101 qualified



eSMP® シリーズ

パワーダイオード製品の小型・薄型パッケージソリューション

IN A
NUTSHELL

eSMP® パッケージ

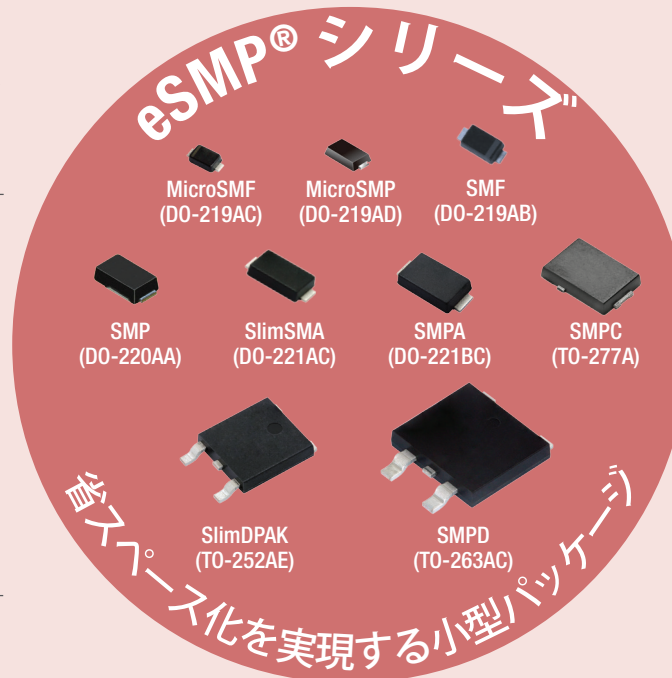
パワーデバイス向けに最適化
した表面実装型パッケージ



- 独自開発パッケージ
- 電力効率の向上
- 高い電流駆動能力



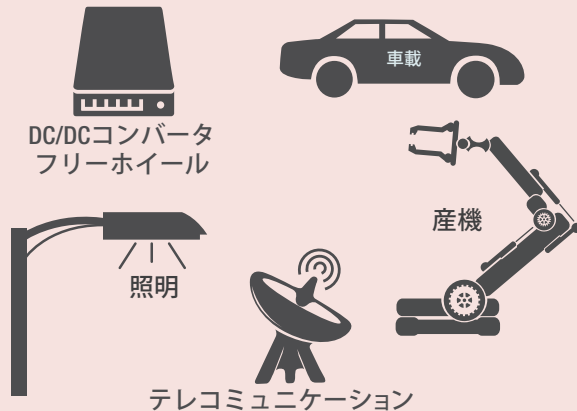
- 熱性能と信頼性の向上に貢献



各種eSMP®パッケージで提供 される製品シリーズ

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- PAR® TVSダイオード
- TRANSZORB® TVS ダイオード
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- アバランシェダイオード
- FRED Pt®ダイオード
- ショットキーダイオード
- 標準・高速リカバリーダイオード
- TMBS® ダイオード
- 超高速リカバリーダイオード

用途



参照リンク:



eSMP® シリーズ製品概要

www.vishay.com/doc?49383

ダイオード (eSMP®シリーズパッケージ)

www.vishay.com/landingpage/tradeshows/diodes/

端子形状が**非対称・対称**なフラット
リードタイプパッケージで提供

技術に関するお問い合わせ先: DiodesAmericas@vishay.com, DiodesEurope@vishay.com, DiodesAsia@vishay.com



eSMP® 系列

用于选定二极管和整流器的小尺寸和低型面高度封装解决方案

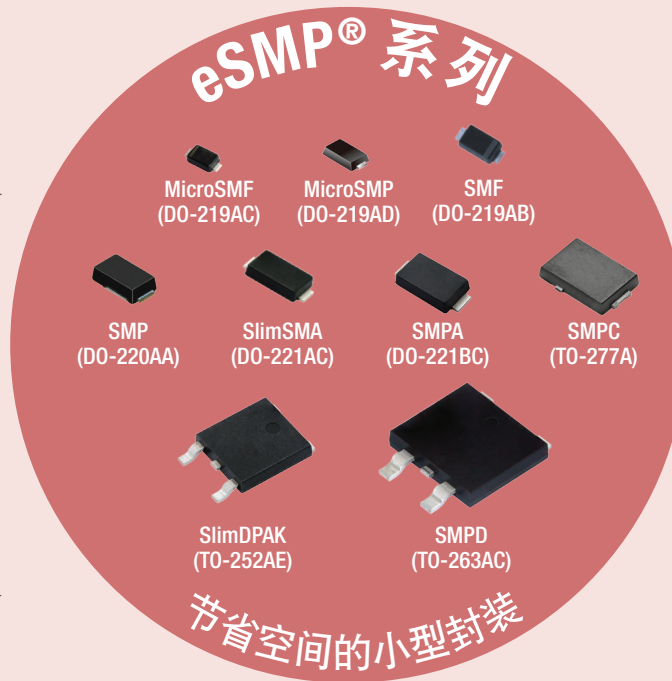
快速了解

eSMP® 封装

增强型表面贴装功率封装



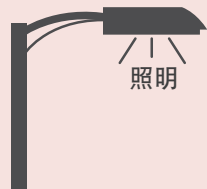
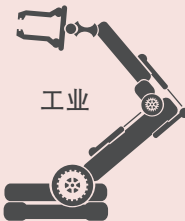
利用可提供更出色**热性能**和**可靠性的独特设计**支持更高的**电流**和**功率效率**



eSMP®系列封装提供的产品技术:

- ESD 保护二极管
- PAR® TVS 二极管
- TRANSZORB® TVS 二极管
- 齐纳二极管
- 雪崩整流器
- FRED Pt® 整流器
- 肖特基整流器
- 标准和快速恢复整流器
- TMBS® 整流器
- 超快恢复整流器

应用



有用链接



eSMP® 系列产品概述:

www.vishay.com/doc?49383

采用 eSMP® 系列封装的二极管/整流器:

www.vishay.com/landingpage/tradeshows/diodes/

提供不对称和对称扁平式封装

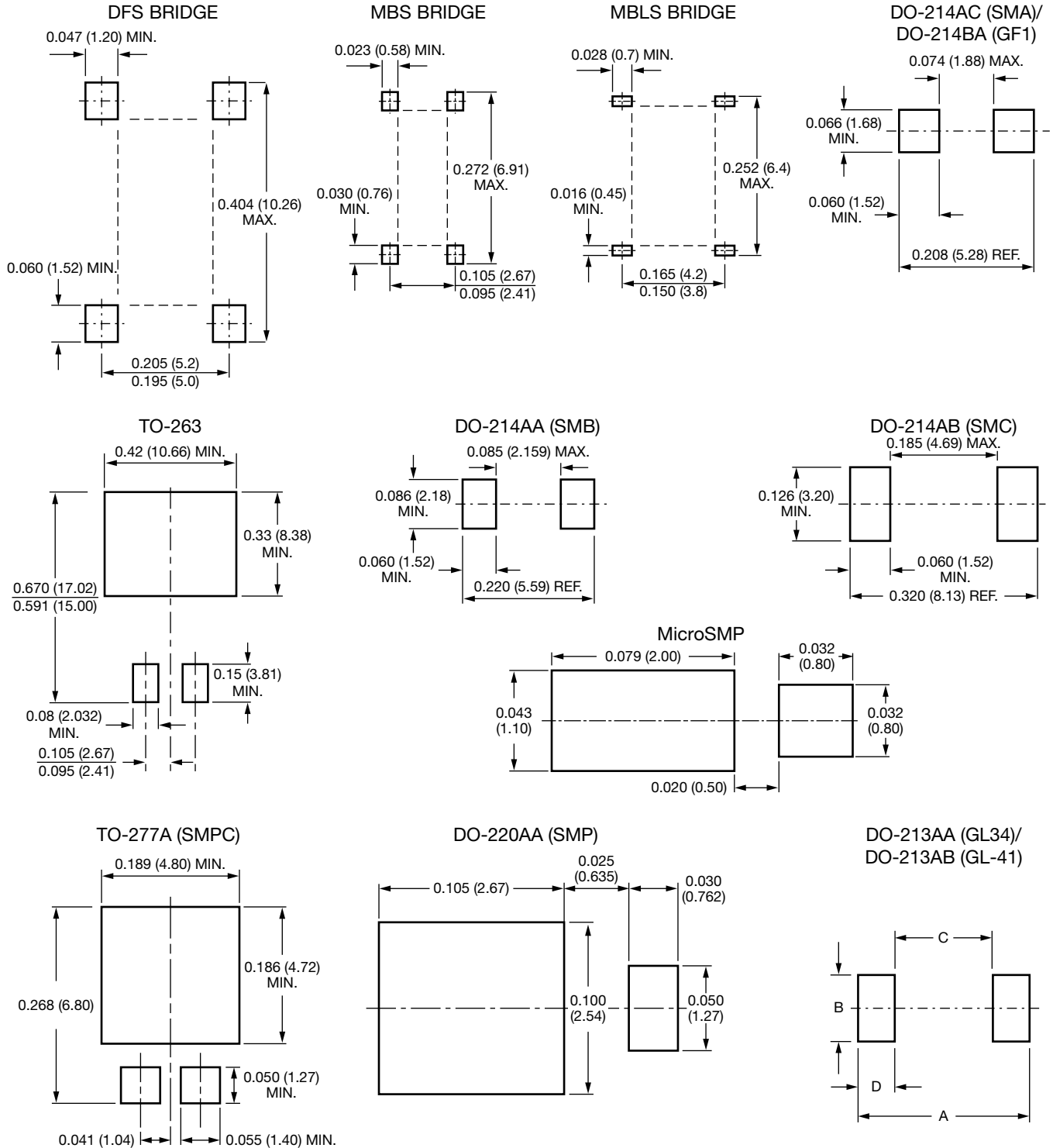
技术问题垂询: DiodesAmericas@vishay.com、DiodesEurope@vishay.com 或 DiodesAsia@vishay.com

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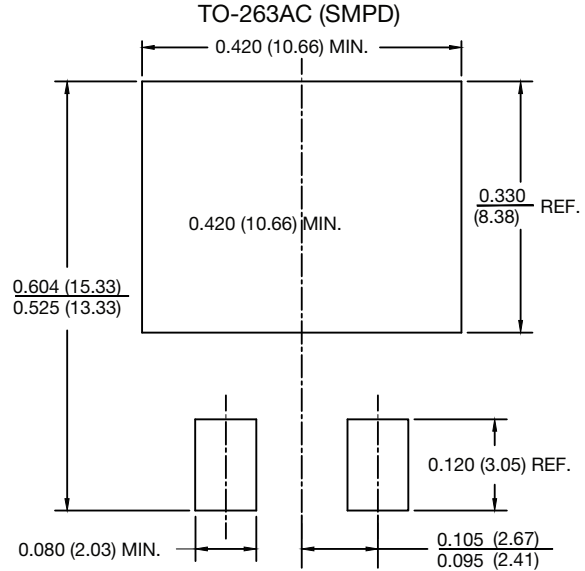
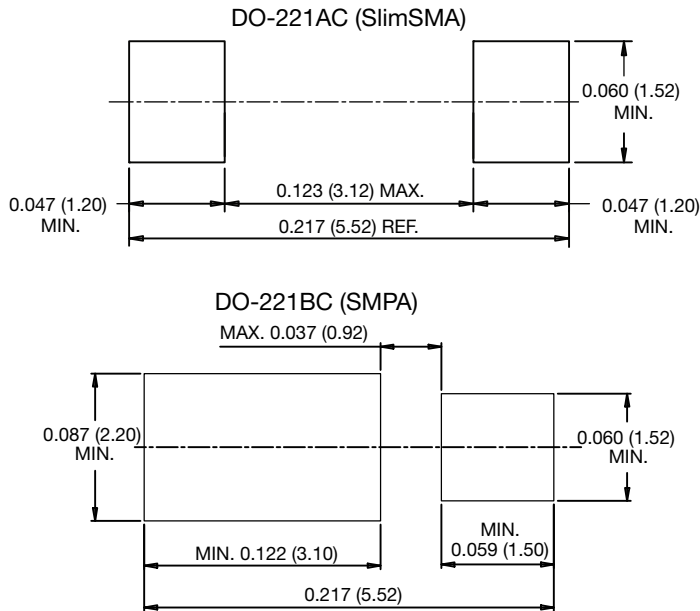
VMN-MS7319-1703

Pad Layouts/Soldering Process

VISHAY GENERAL SEMICONDUCTOR RECOMMENDED MINIMUM MOUNTING PAD LAYOUT SIZES FOR THE SURFACE MOUNT RECTIFIER



All dimensions in inches (millimeters)



DIMENSIONS in inches (millimeters)		
	DO-213AA (GL34)	DO-213AB (GL41)
A	0.177 (4.5) ref.	0.236 (6.0) ref.
B	0.079 (2.0) min.	0.118 (3.0) min.
C	0.079 (2.0) max.	0.138 (3.5) max.
D	0.050 (1.25) min.	0.050 (1.25) min.

VISHAY GENERAL SEMICONDUCTOR RECOMMENDED SOLDERING PROCESS

Through hole device (THD) and surface mount device (SMD) imply different soldering technologies leading to different constraints.

In THD, the package body is exposed to relatively low temperatures (< 150 °C) because the lead extremities are only dipped in the soldering alloy, whereas in SMD the whole package body is exposed to a very high temperature (> 240 °C) during reflow soldering process.

In addition, molding compounds used for encapsulation absorb moisture from the ambient medium. During rapid heating in solder reflow process; this absorbed moisture can vaporize, generating pressure at lead frame pad/silicon to plastic interfaces in the package, with a risk of package cracking and potential degradation of device reliability.

Wave soldering with SMD packages is not recommended because the thermal shock associated with package body solder dipping may induce internal structural damage to the package (interface delamination) that may affect long term reliability.

SMD package characterizations performed as a standard by Vishay only induce Solder Reflow Resistance assessment.

JEDEC JESD A111 recommends that wave soldering of SMD packages should be evaluated by the USER, because the stress induced inside the package is very dependant of solder process parameters.

Due to the higher melting point of lead (Pb)-free alloys, the temperature of the solder pot will also increase to improve solderability and shorten contact times. For AgSnCu with melting point of 217 °C, the solder pot temperature will be between 250 °C to 270 °C or as high as 260 °C to 280 °C for SnCu.

RECOMMENDED WAVE SOLDERING PROFILE FOR THROUGH HOLE COMPONENTS

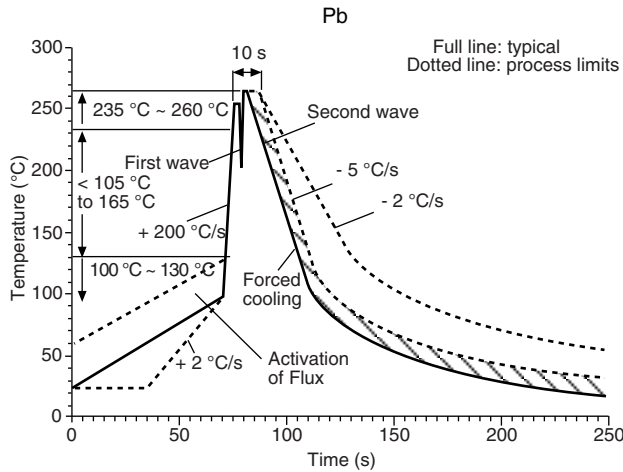
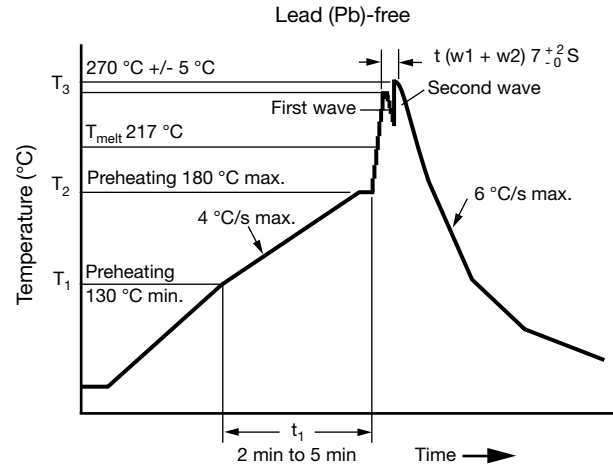


Fig. 1



Notes

- Temperature jump from T_2 to T_3 (w_1): 150 °C max.
- Time from 25 °C to T_3 (wave temp.): 8 min max.

Fig. 2

REFLOW FOR SURFACE MOUNTED COMPONENTS

TABLE 1 - CLASSIFICATION REFLOW PROFILE		
PROFILE FEATURE	Sn-Pb EUTECTIC ASSEMBLY	LEAD (Pb)-FREE ASSEMBLY
Preheat and soak		
Temperature min. ($T_{Smin.}$)	100 °C	150 °C
Temperature max. ($T_{Smax.}$)	150 °C	200 °C
Time ($T_{Smin.}$ to $T_{Smax.}$) (t_s)	60 s to 120 s	60 s to 120 s
Average ramp-up rate ($T_{Smax.}$ to T_p)	3 °C/s maximum	
Liquidous temperature (T_L)	183 °C	217 °C
Time to liquidous (t_L)	60 s to 150 s	60 s to 150 s
Peak package temperature (T_p) ⁽¹⁾	See classification temperature in table 2	See classification temperature in table 3
Time (t_p) ⁽²⁾ with 5 °C of the specified classification temperature (T_C)	20 s ⁽²⁾	30 s ⁽²⁾
Average ramp-down rate (T_p to $T_{Smax.}$)	6 °C/s maximum	
Time 25 °C to peak temperature	6 min maximum	8 min maximum

Notes

- (1) Tolerance for peak profile temperature (T_p) is defined as a supplier minimum and user maximum
- (2) Tolerance for time at peak profile temperature (T_p) is defined as a supplier minimum and user maximum

REFLOW PROFILE

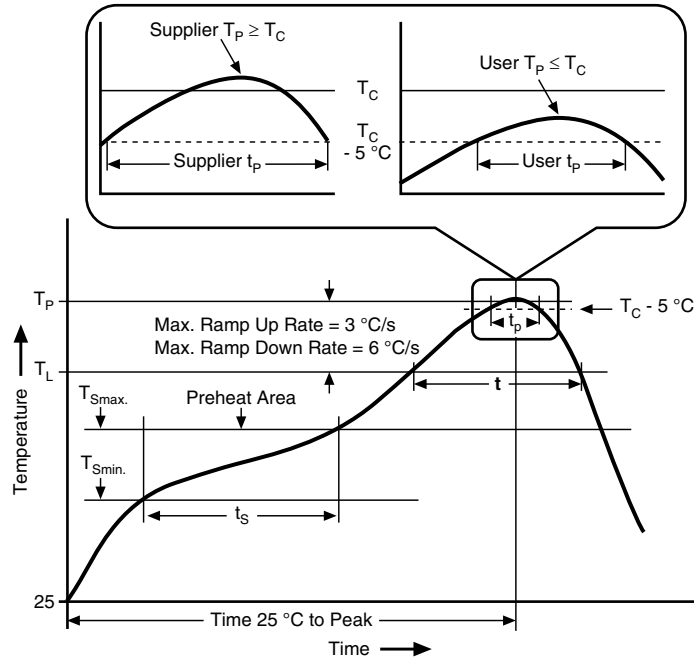


Fig. 3

TABLE 2 - Sn-Pb EUTECTIC PROCESS PACKAGE PEAK REFLOW TEMPERATURES		
PACKAGE THICKNESS	VOLUME mm ³ < 350	VOLUME mm ³ ≥ 350
< 2.5 mm	235 °C	220 °C
≥ 2.5 mm	220 °C	220 °C

TABLE 3 - LEAD (Pb) - FREE PROCESS PACKAGE CLASSIFICATION REFLOW TEMPERATURES			
PACKAGE THICKNESS	VOLUME mm ³ < 350	VOLUME mm ³ 350 TO 2000	VOLUME mm ³ > 2000
< 1.6 mm	260 °C	260 °C	260 °C
1.6 mm to 2.5 mm	260 °C	250 °C	245 °C
≥ 2.5 mm	250 °C	245 °C	245 °C

Tolerance: The device manufacturer/supplier shall assure process compatibility up to and including the stated classification temperature at the rated MSL level.

Notes

- Package volume excludes external terminals (balls, bumps, lands, leads) and/or non-integral heatsinks.
- The maximum component temperature reached during reflow depends on package thickness and volume. The use of convection reflow processes reduces the thermal gradients between packages. However, thermal gradients due to differences in thermal mass of SMD packages may still exist.
- Recommended soldering process is accordance with J-STD-020D.



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